如何在IEEE發表高品質研究並提高學術影響力

Cindy Tu，Hinton產品&行銷經理

本期主題

- 為您的研究發表選擇合適的出版物
- 投稿實踐與注意事項
- 編輯和審稿人在尋找什麼
- 如何提高研究的可見度和影響力
- IEEE 2023 OA 投稿優惠詳解與實踐流程

為您的研究發表選擇合適的出版物

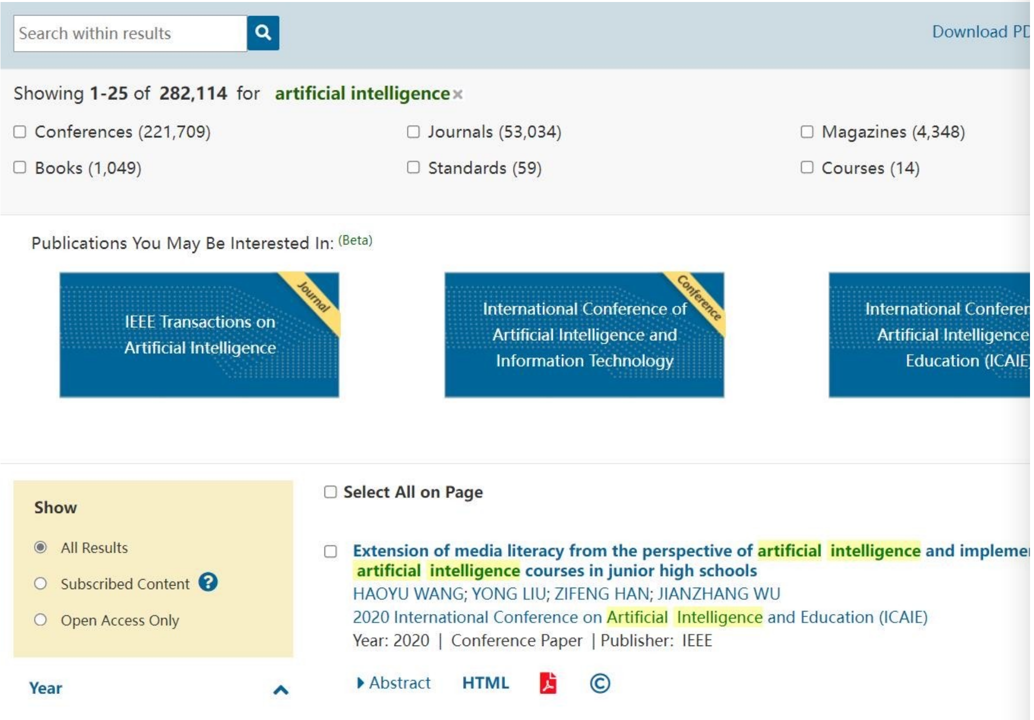
投稿IEEE期刊還是會議?

- 期刊文章是研究工作和最終結果的完整展示
  - 展示原創研究結果
  - 做出清晰推論，並輔以資料支援
- 會議文章可以是正在進行沒有完成的研究
  - 可展示初期成果或強調最近工作
  - 獲得非正式回饋用於後續研究
- 會議論文通常短於期刊論文,細節和參考文獻也少些

200+
Journals, Transactions, Magazines

2,000+
Conferences

篩選與研究領域最相關的出版物



Search within results

Download PD

Showing **1-25** of **282,114** for **artificial intelligence** ×

☐ Conferences (221,709)
☐ Journals (53,034)
☐ Magazines (4,348)
☐ Books (1,049)
☐ Standards (59)
☐ Courses (14)

Publications You May Be Interested In: (Beta)

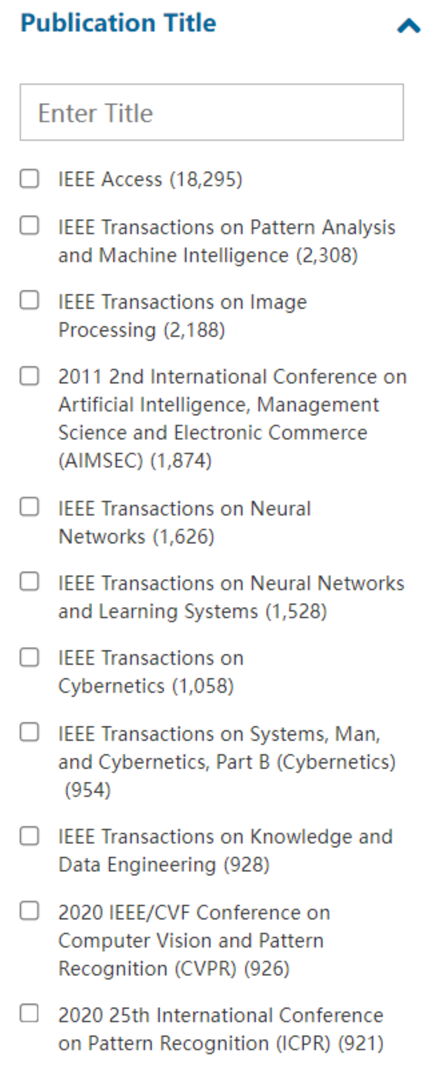
Show

● All Results
○ Subscribed Content
○ Open Access Only

Year

☐ **Select All on Page**

☐ **Extension of media literacy from the perspective of artificial intelligence and impleme artificial intelligence courses in junior high schools**
HAOYU WANG; YONG LIU; ZIFENG HAN; JIANZHANG WU
2020 International Conference on Artificial Intelligence and Education (ICAIE)
Year: 2020 | Conference Paper | Publisher: IEEE



Publication Title

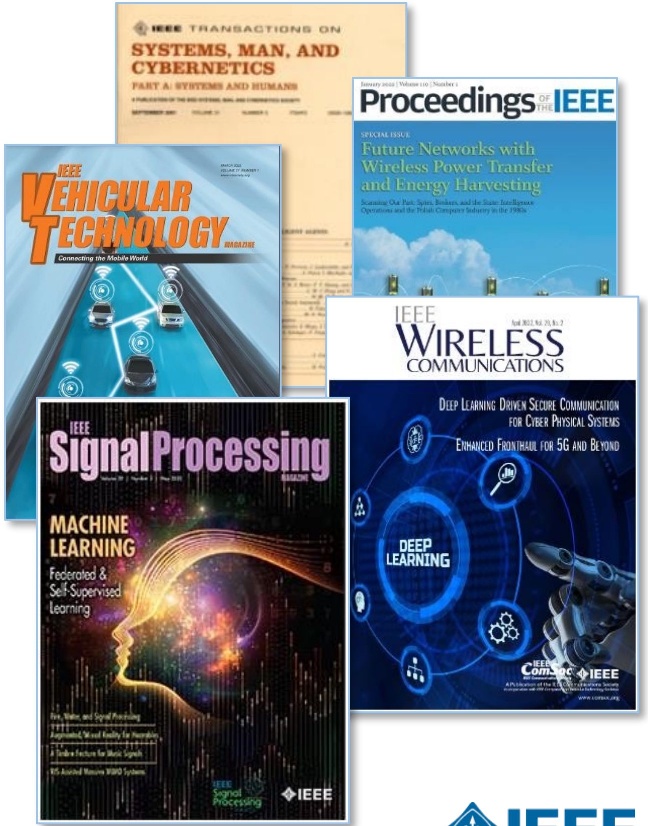
Enter Title

☐ IEEE Access (18,295)
☐ IEEE Transactions on Pattern Analysis and Machine Intelligence (2,308)
☐ IEEE Transactions on Image Processing (2,188)
☐ 2011 2nd International Conference on Artificial Intelligence, Management Science and Electronic Commerce (AIMSEC) (1,874)
☐ IEEE Transactions on Neural Networks (1,626)
☐ IEEE Transactions on Neural Networks and Learning Systems (1,528)
☐ IEEE Transactions on Cybernetics (1,058)
☐ IEEE Transactions on Systems, Man, and Cybernetics, Part B (Cybernetics) (954)
☐ IEEE Transactions on Knowledge and Data Engineering (928)
☐ 2020 IEEE/CVF Conference on Computer Vision and Pattern Recognition (CVPR) (926)
☐ 2020 25th International Conference on Pattern Recognition (ICPR) (921)

IEEE期刊在眾多領域具有領先優勢

IEEE journals score in top tier in latest Journal Citation Reports™

- 8 of the top 10 journals in Electrical & Electronic Engineering
- 9 of the top 10 journals in Telecommunications
- 3 of the top 5 journals in Automation & Control Systems
- 3 of the top 5 journals in Artificial Intelligence
- 3 of the top 5 journals in Cybernetics
- 3 of the top 5 journals in Computer Hardware & Architecture
- 3 of the top 5 journals in Information Systems
- 3 of the top 5 journals in Software Engineering
- 3 of the top 5 journals in Imaging Science



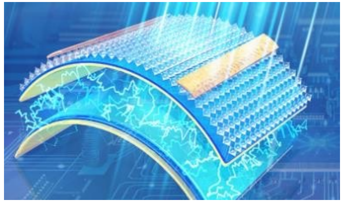
For more information, visit www.ieee.org/citations

** Source: 2021 Journal Citation Reports from Clarivate, released June 2022*

IEEE 新刊

2022年新刊

- IEEE Transactions on **Signal and Power Integrity**
- IEEE Journal on **Flexible Electronics**



2023年新刊

- IEEE Transactions on **AgriFood Electronics**
- IEEE **Electron Devices** Magazine
- IEEE Transactions on **Energy Markets**, Policy and Regulation
- IEEE Transactions on Industrial **Cyber-Physical Systems**
- IEEE Transactions on **Radar Systems**

*Please note this is a tentative list and is subject to change.

學術期刊

- **Journals**, **Transactions**, and **Letters** are the primary means for publishing technical papers concerning original work in IEEE fields of interest.
  - The primary purpose of Journals, Transactions, and Letters is to disclose and provide a permanent archival record of original technical work that advances the state of the art or provides novel insights.
  - Letters are for the publication of brief papers, usually three to four pages in length.

EEE TRANSACTIONS ON
OMMUNICATIONS

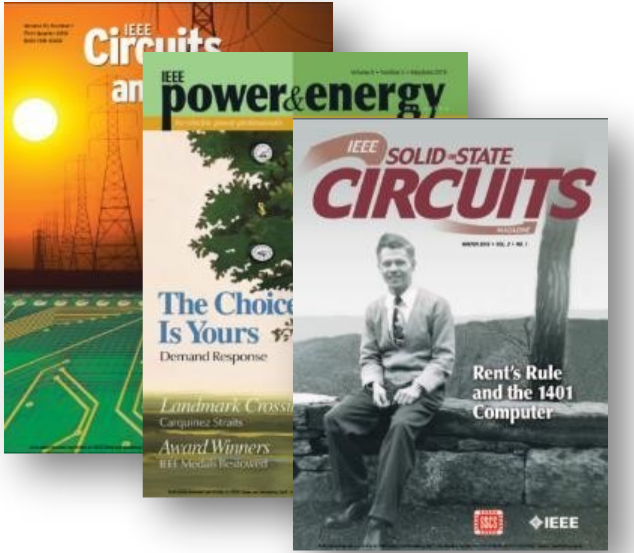
IEEE
SENSORS JOURNAL

IEEE
SIGNAL PROCESSING LETTERS

IEEE

技術雜誌

- **Magazines** are characterized by regular and continuing issues with significant technical content in addition to general news and regular columns
  - IEEE Communications Magazine
  - IEEE Microwave Magazine
  - IEEE Signal Processing Magazine
  - IEEE Instrumentation & Measurement Magazine
  - ……



以MTT刊物為例

IEEE TRANSACTIONS ON
MICROWAVE THEORY
AND TECHNIQUES

IEEE

	Transactions	Letters	Magazine
New Research Article	YES(6pages, over-length charges)	YES(3pages)	NO
Tutorial Article	YES(at expert level)	NO	YES(at Fundamental To Intermediate level)
Application Note	NO	NO	YES
Review Article	YES(at expert level)	NO	YES(at Fundamental To Intermediate level)

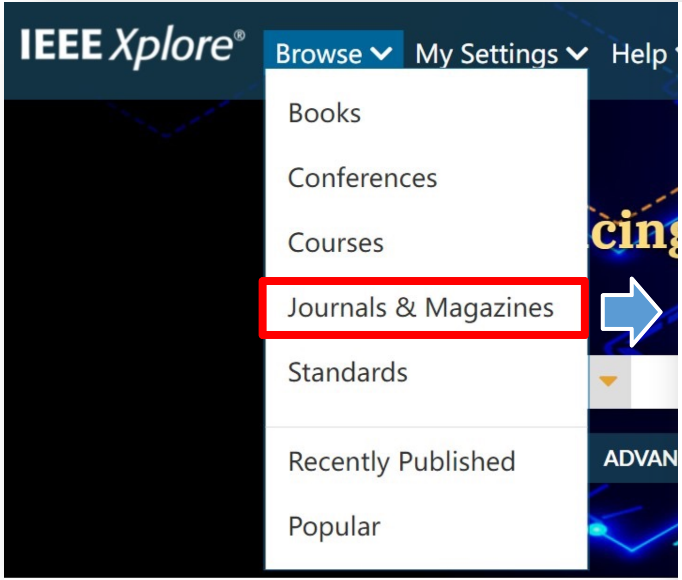
- **Research Article**: Papers in the journals use the IEEE standard format and must include a Title, Abstract, Introduction, Technical Content, Conclusions, and References. The transactions also include the author biographies.
- **Tutorial:** Unique presentation of known material. Valuable methodologies, exhaustive references
- **Application Note:** Describe current application of technology: circuits, systems, models, concepts.
- **Review:** Historical account of field, exhaustive references, explanation of state-of-the-art, indications of future research

進一步瞭解期刊

- 一旦確定了4-5本目標期刊，下一步是研究“Aims and Scope” 以瞭解到底該刊傾向於何種類型的文章
  - 主編
  - 編委成員

- 閱讀部分期刊收錄的文章，判斷該期刊的讀者群是否吻合

在 IEEE Xplore 尋找合適的期刊



Browse Journals & Magazines

Browse Titles

Displaying Results **1-2** of **2** for **internet of things** ✕

Refine results by

Show

- ● All Results
- ○ Open Access Titles Only
- ○ Titles with Some Open Access

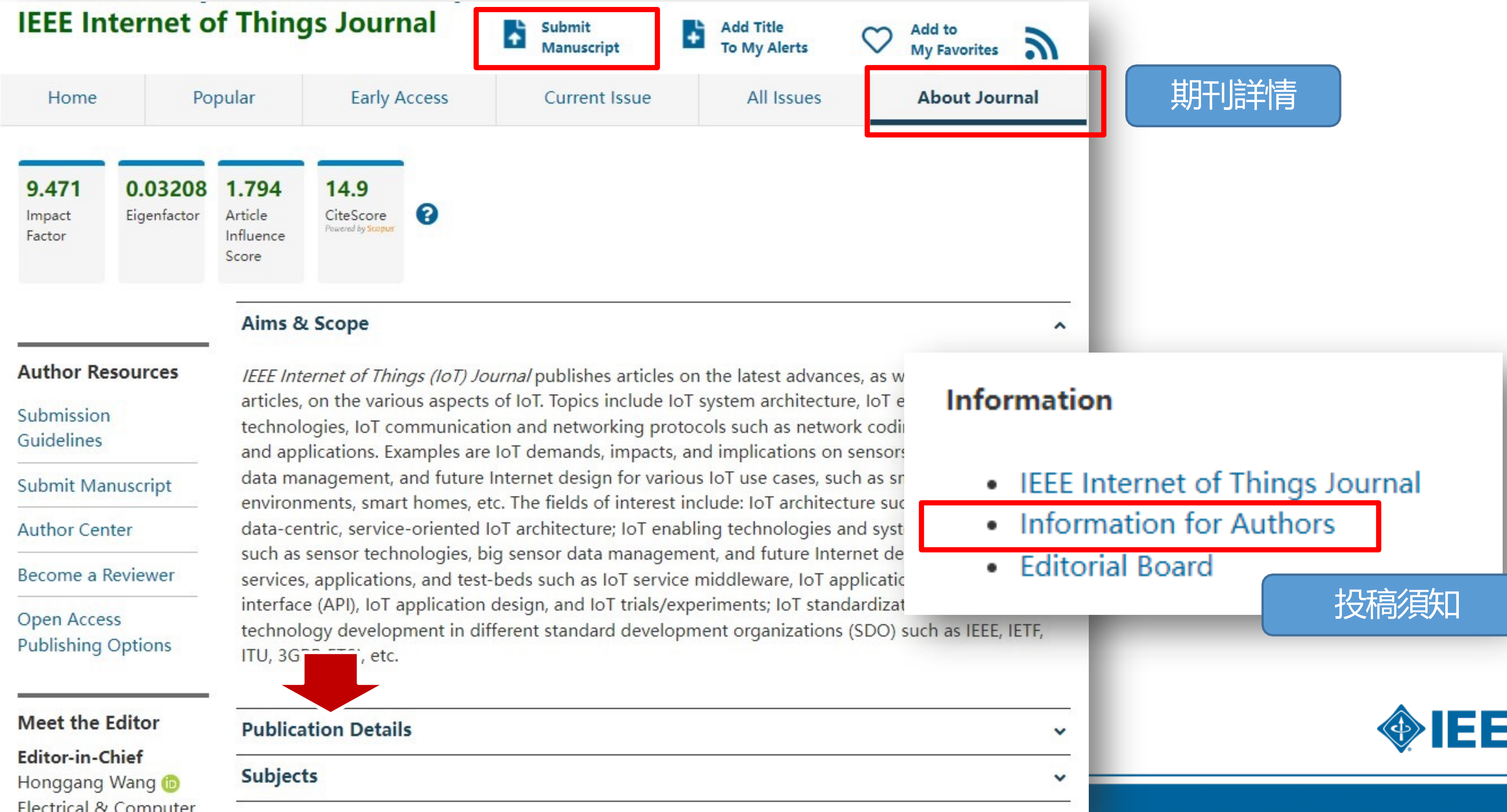
☐ Show active titles only

IEEE Internet of Things Journal
Publisher: IEEE **Years:** 2014 - Present Most Recent Issue

IEEE Internet of Things Magazine
Publisher: IEEE **Years:** 2018 - Present Most Recent Issue

篩選OA屬性

期刊詳情與投稿



投稿

期刊詳情

投稿須知

IEEE Internet of Things Journal

9.471	0.03208	1.794	14.9
Impact Factor	Eigenfactor	Article Influence Score	CiteScore Powered by Scopus

Aims & Scope

IEEE Internet of Things (IoT) Journal publishes articles on the latest advances, as w articles, on the various aspects of IoT. Topics include IoT system architecture, IoT e technologies, IoT communication and networking protocols such as network codi and applications. Examples are IoT demands, impacts, and implications on sensors data management, and future Internet design for various IoT use cases, such as sr environments, smart homes, etc. The fields of interest include: IoT architecture suc data-centric, service-oriented IoT architecture; IoT enabling technologies and syst such as sensor technologies, big sensor data management, and future Internet de services, applications, and test-beds such as IoT service middleware, IoT applicatio interface (API), IoT application design, and IoT trials/experiments; IoT standardizat technology development in different standard development organizations (SDO) such as IEEE, IETF, ITU, 3G , etc.

Author Resources

- Submission Guidelines
- Submit Manuscript
- Author Center
- Become a Reviewer
- Open Access Publishing Options

Meet the Editor

Editor-in-Chief
Honggang Wang
Electrical & Computer

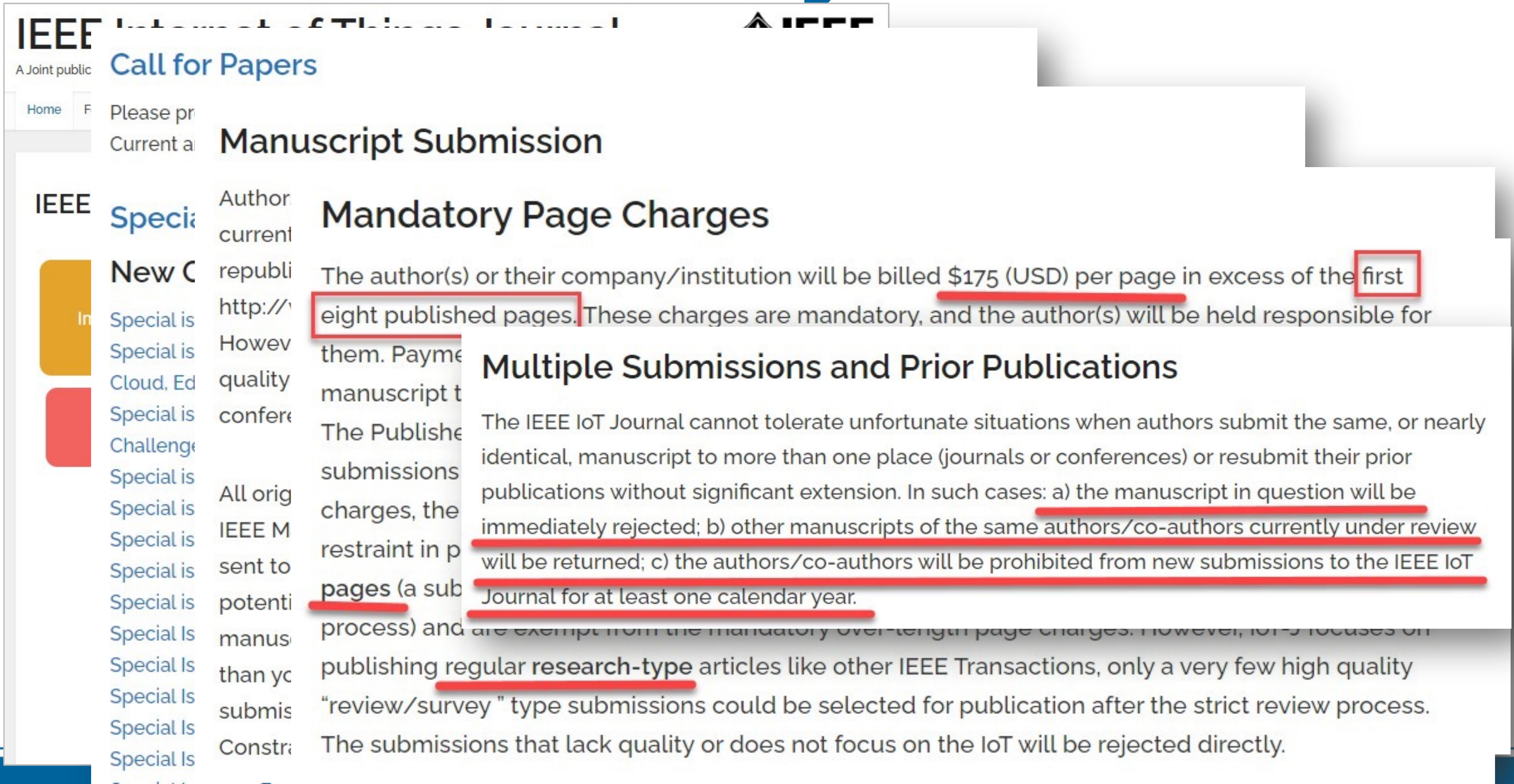
Publication Details

Subjects

Information

- IEEE Internet of Things Journal
- Information for Authors
- Editorial Board

舉例: IEEE Internet of Things Journal



IEEE Internet of Things Journal

A Joint public

Home F

IEEE

In

Call for Papers

Please pr
Current a

Speci

New C

Special is
Special is
Cloud, Ed
Special is
Challeng
Special is
Special is
Special is
Special is
Special is
Special Is
Special Is
Special Is
Special Is
Special Is

Manuscript Submission

Author
current
republi
http://
Howev
quality
confere

All orig
IEEE M
sent to
potenti
manus
than yo
submis
Constr

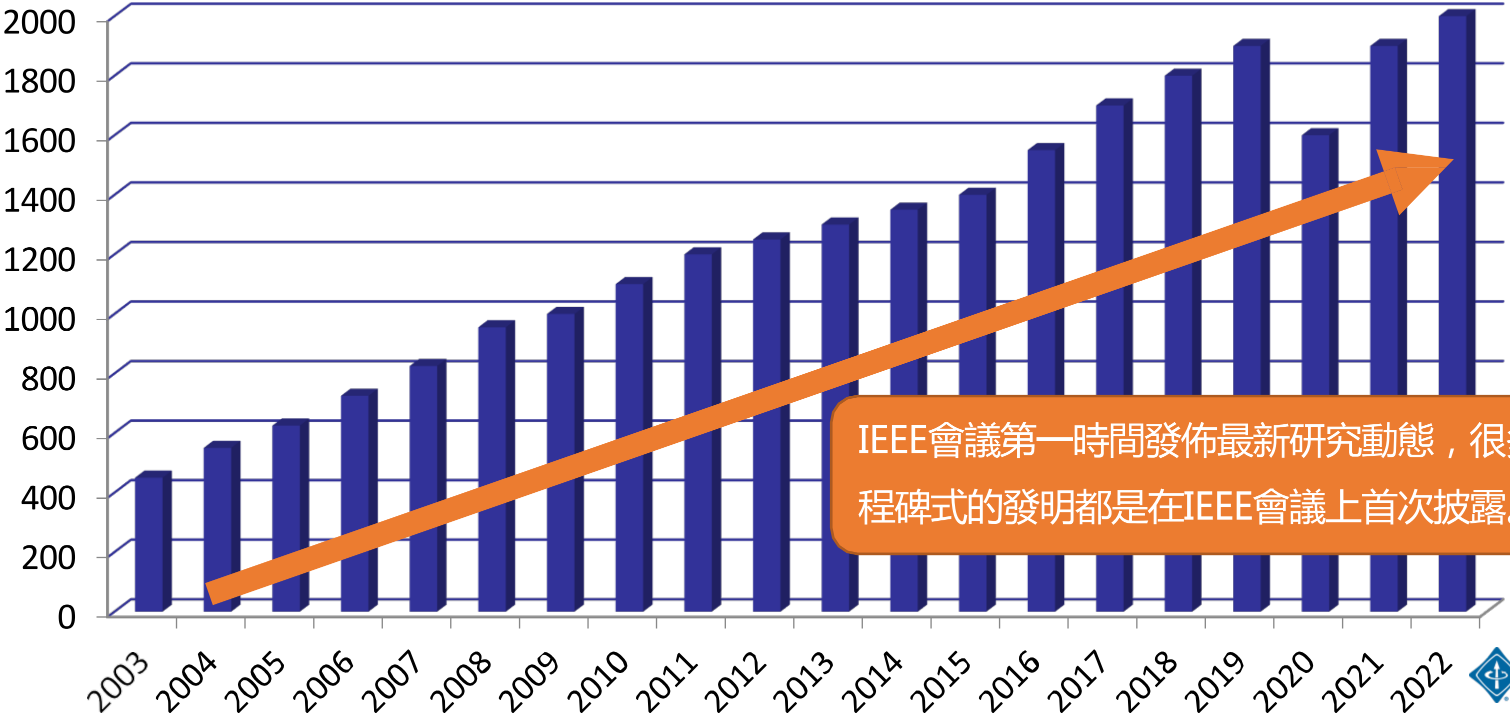
Mandatory Page Charges

The author(s) or their company/institution will be billed $175 (USD) per page in excess of the first eight published pages. These charges are mandatory, and the author(s) will be held responsible for them. Payme
manuscript t
The Publishe
submissions
charges, the
restraint in p
pages (a sub
process) and are exempt from the mandatory over-length page charges. However, IoT-J focuses on publishing regular research-type articles like other IEEE Transactions, only a very few high quality "review/survey " type submissions could be selected for publication after the strict review process. The submissions that lack quality or does not focus on the IoT will be rejected directly.

Multiple Submissions and Prior Publications

The IEEE IoT Journal cannot tolerate unfortunate situations when authors submit the same, or nearly identical, manuscript to more than one place (journals or conferences) or resubmit their prior publications without significant extension. In such cases: a) the manuscript in question will be immediately rejected; b) other manuscripts of the same authors/co-authors currently under review will be returned; c) the authors/co-authors will be prohibited from new submissions to the IEEE IoT Journal for at least one calendar year.

IEEE會議逐年增加



IEEE會議第一時間發佈最新研究動態，很多里程碑式的發明都是在IEEE會議上首次披露。

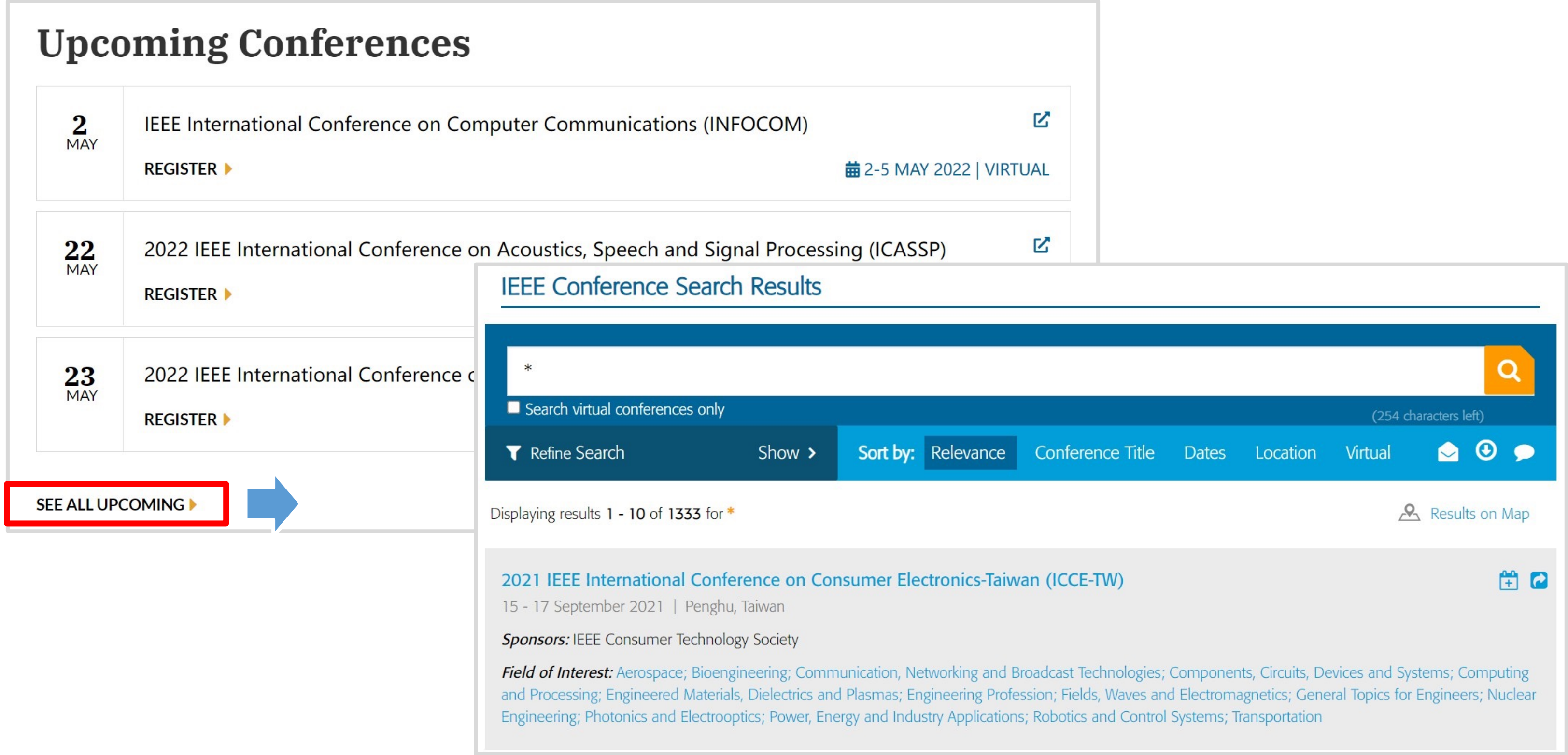
會議相關的幾個概念

- Congress
- Conference
- Symposium
- Seminar
- Workshop
- …

如何選擇高品質會議

- H指數
- EI索引
- 技術協會網站
- 會議歷史
- 會議組委會
- 會議論文品質
- ……

IEEE Xplore主頁底部查詢即將舉辦的IEEE會議



Upcoming Conferences

2 MAY
IEEE International Conference on Computer Communications (INFOCOM)
REGISTER ▸
2-5 MAY 2022 | VIRTUAL

22 MAY
2022 IEEE International Conference on Acoustics, Speech and Signal Processing (ICASSP)
REGISTER ▸

23 MAY
2022 IEEE International Conference c
REGISTER ▸

SEE ALL UPCOMING ▸

IEEE Conference Search Results

*

☐ Search virtual conferences only

(254 characters left)

Displaying results 1 - 10 of 1333 for *

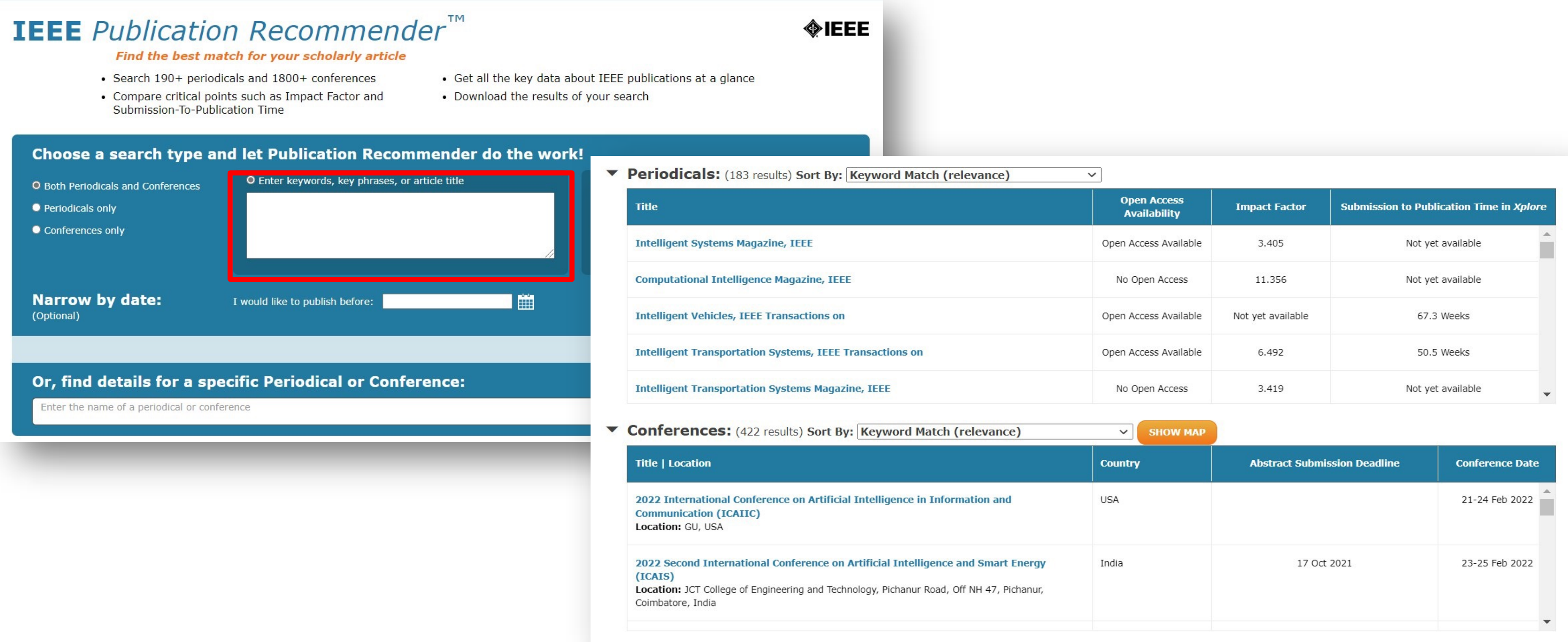
Results on Map

2021 IEEE International Conference on Consumer Electronics-Taiwan (ICCE-TW)
15 - 17 September 2021 | Penghu, Taiwan

Sponsors: IEEE Consumer Technology Society

Field of Interest: Aerospace; Bioengineering; Communication, Networking and Broadcast Technologies; Components, Circuits, Devices and Systems; Computing and Processing; Engineered Materials, Dielectrics and Plasmas; Engineering Profession; Fields, Waves and Electromagnetics; General Topics for Engineers; Nuclear Engineering; Photonics and Electrooptics; Power, Energy and Industry Applications; Robotics and Control Systems; Transportation

IEEE Publication Recommender™



IEEE *Publication Recommender*™

Find the best match for your scholarly article

- Search 190+ periodicals and 1800+ conferences
- Compare critical points such as Impact Factor and Submission-To-Publication Time
- Get all the key data about IEEE publications at a glance
- Download the results of your search

Choose a search type and let Publication Recommender do the work!

● Both Periodicals and Conferences
○ Periodicals only
○ Conferences only

● Enter keywords, key phrases, or article title

Narrow by date:
(Optional)

I would like to publish before:

Or, find details for a specific Periodical or Conference:

Enter the name of a periodical or conference

Periodicals: (183 results) **Sort By:** Keyword Match (relevance)

Title	Open Access Availability	Impact Factor	Submission to Publication Time in *Xplore*
Intelligent Systems Magazine, IEEE	Open Access Available	3.405	Not yet available
Computational Intelligence Magazine, IEEE	No Open Access	11.356	Not yet available
Intelligent Vehicles, IEEE Transactions on	Open Access Available	Not yet available	67.3 Weeks
Intelligent Transportation Systems, IEEE Transactions on	Open Access Available	6.492	50.5 Weeks
Intelligent Transportation Systems Magazine, IEEE	No Open Access	3.419	Not yet available

Conferences: (422 results) **Sort By:** Keyword Match (relevance) SHOW MAP

Title | Location	Country	Abstract Submission Deadline	Conference Date
2022 International Conference on Artificial Intelligence in Information and Communication (ICAIIC) **Location:** GU, USA	USA		21-24 Feb 2022
2022 Second International Conference on Artificial Intelligence and Smart Energy (ICAIS) **Location:** JCT College of Engineering and Technology, Pichanur Road, Off NH 47, Pichanur, Coimbatore, India	India	17 Oct 2021	23-25 Feb 2022

http://publication-recommender.ieee.org/home

投稿實踐與注意事項

期刊詳情與投稿

投稿

Browse Journals & Magazines > IEEE Internet of Things Journa... ?

IEEE Internet of Things Journal

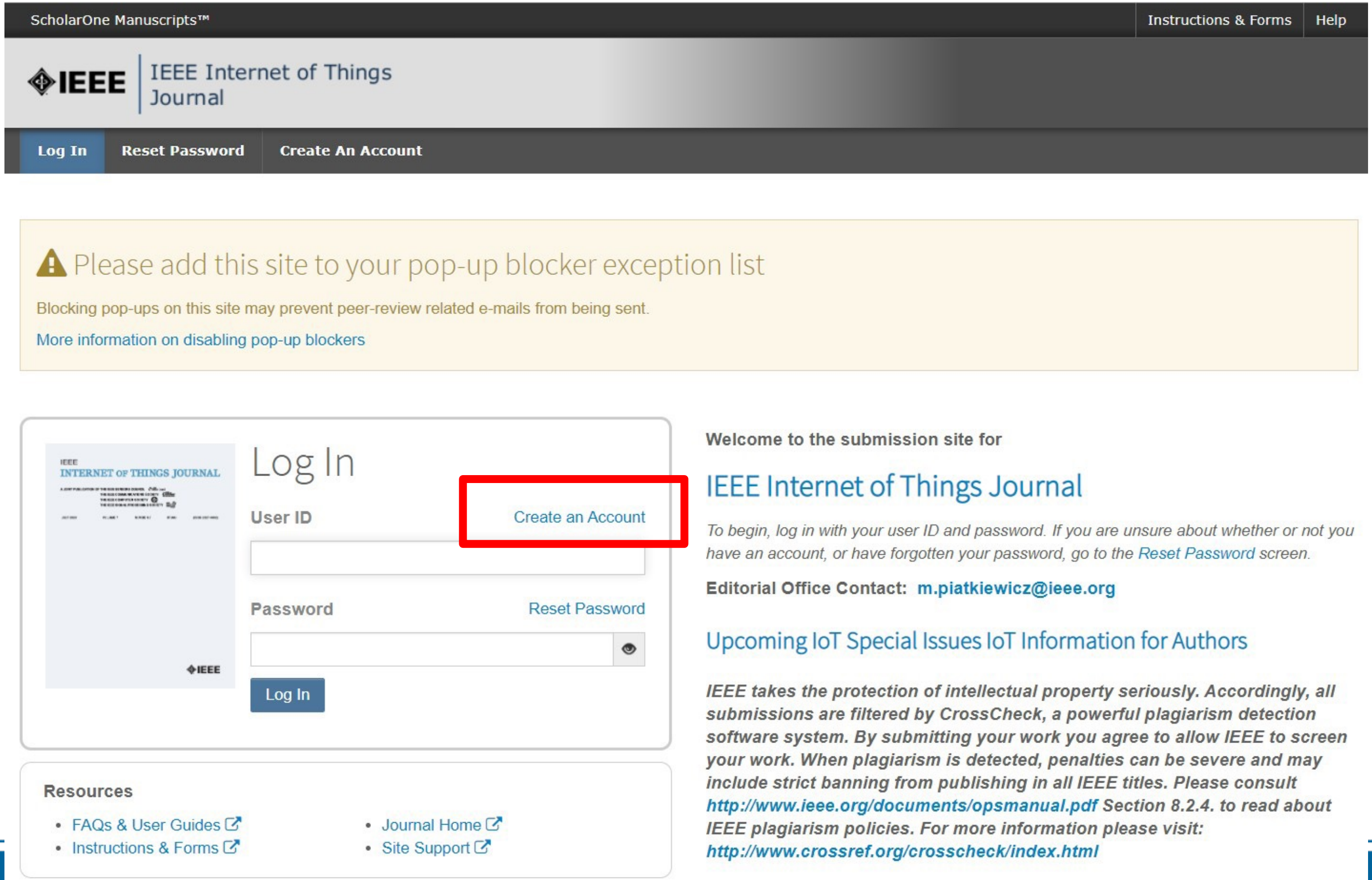
10.238	0.05014	2.024	17.1
Impact Factor	Eigenfactor	Article Influence Score	CiteScore Powered by Scopus

Aims & Scope

IEEE Internet of Things (IoT) Journal publishes articles on the latest advances, as well as review articles, on the various aspects of IoT. Topics include IoT system architecture, IoT enabling technologies, IoT communication and networking protocols such as network coding, and IoT services and applications. Examples are IoT demands, impacts, and implications on sensors technologies, big data management, and future internet design for various IoT use cases, such as smart cities, smart environments, smart homes, etc. The fields of interest include: IoT architecture such as things-centric, data-centric, service-oriented IoT architecture; IoT enabling technologies and systematic integration such as sensor technologies, big sensor data management, and future Internet design for IoT; IoT

Author Resources

線上投稿平臺



Please add this site to your pop-up blocker exception list

Blocking pop-ups on this site may prevent peer-review related e-mails from being sent.

More information on disabling pop-up blockers

Welcome to the submission site for

IEEE Internet of Things Journal

To begin, log in with your user ID and password. If you are unsure about whether or not you have an account, or have forgotten your password, go to the Reset Password screen.

Editorial Office Contact: **m.piatkiewicz@ieee.org**

Upcoming IoT Special Issues IoT Information for Authors

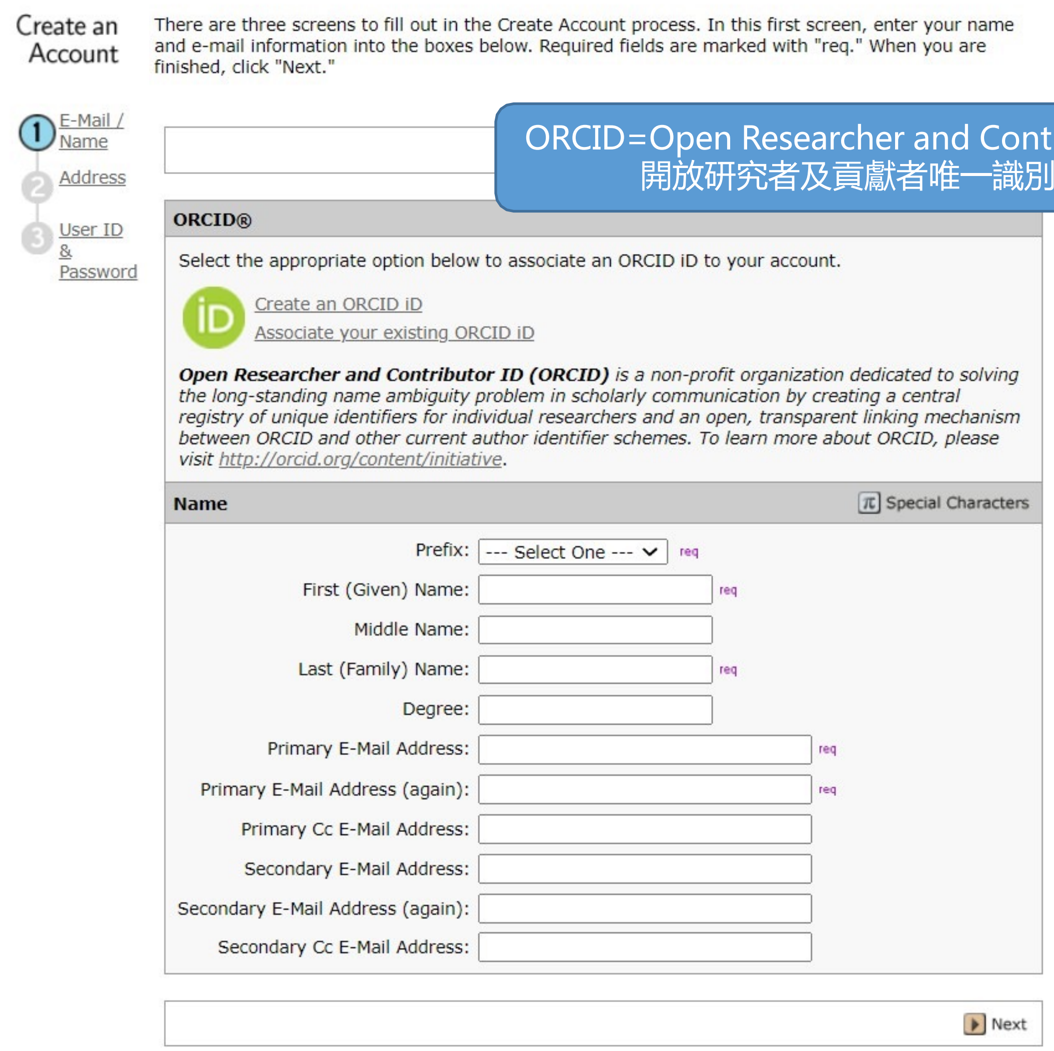
IEEE takes the protection of intellectual property seriously. Accordingly, all submissions are filtered by CrossCheck, a powerful plagiarism detection software system. By submitting your work you agree to allow IEEE to screen your work. When plagiarism is detected, penalties can be severe and may include strict banning from publishing in all IEEE titles. Please consult http://www.ieee.org/documents/opsmanual.pdf Section 8.2.4. to read about IEEE plagiarism policies. For more information please visit: http://www.crossref.org/crosscheck/index.html

Resources

- FAQs & User Guides
- Instructions & Forms
- Journal Home
- Site Support

註冊作者帳號

ORCID=Open Researcher and Contributor ID
開放研究者及貢獻者唯一識別碼



Create an Account

There are three screens to fill out in the Create Account process. In this first screen, enter your name and e-mail information into the boxes below. Required fields are marked with "req." When you are finished, click "Next."

1. E-Mail / Name
2. Address
3. User ID & Password

ORCID®

Select the appropriate option below to associate an ORCID iD to your account.

Create an ORCID iD

Associate your existing ORCID iD

Open Researcher and Contributor ID (ORCID) *is a non-profit organization dedicated to solving the long-standing name ambiguity problem in scholarly communication by creating a central registry of unique identifiers for individual researchers and an open, transparent linking mechanism between ORCID and other current author identifier schemes. To learn more about ORCID, please visit http://orcid.org/content/initiative.*

Name

Prefix: --- Select One --- req

First (Given) Name: req

Middle Name:

Last (Family) Name: req

Degree:

Primary E-Mail Address: req

Primary E-Mail Address (again): req

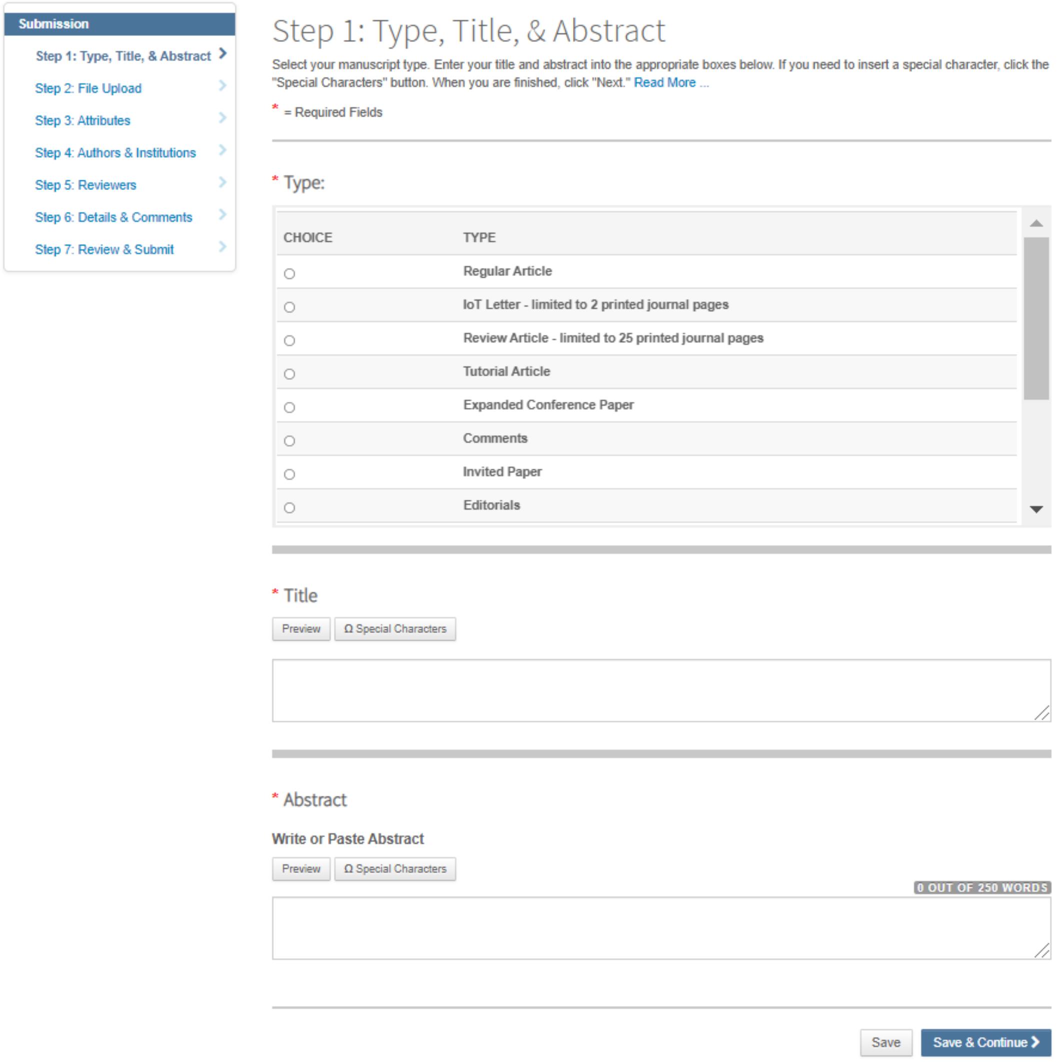
Primary Cc E-Mail Address:

Secondary E-Mail Address:

Secondary E-Mail Address (again):

Secondary Cc E-Mail Address:

輸入題目和文摘



Step 1: Type, Title, & Abstract

Select your manuscript type. Enter your title and abstract into the appropriate boxes below. If you need to insert a special character, click the "Special Characters" button. When you are finished, click "Next." Read More ...

* = Required Fields

* Type:

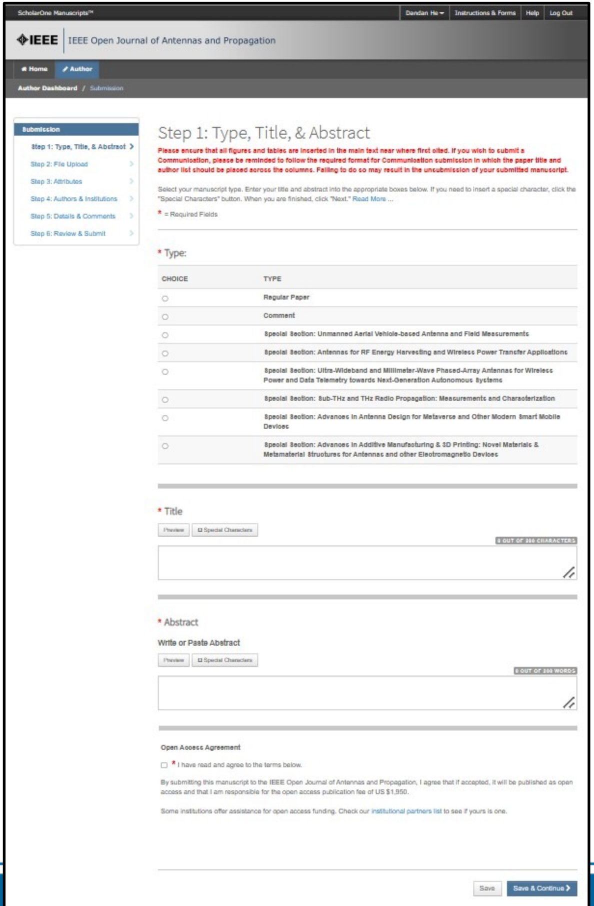
CHOICE	TYPE
○	Regular Article
○	IoT Letter - limited to 2 printed journal pages
○	Review Article - limited to 25 printed journal pages
○	Tutorial Article
○	Expanded Conference Paper
○	Comments
○	Invited Paper
○	Editorials

* Title

* Abstract

Write or Paste Abstract

輸入題目和文摘



Step 1: Type, Title, & Abstract

Please ensure that all figures and tables are inserted in the main text near where first cited. If you wish to submit a Communication, please be reminded to follow the required format for Communication submission in which the paper title and author list should be placed across the columns. Failing to do so may result in the unsubmission of your submitted manuscript.

Select your manuscript type. Enter your title and abstract into the appropriate boxes below. If you need to insert a special character, click the "Special Characters" button. When you are finished, click "Next." Read More ...

* = Required Fields

* Type:

CHOICE	TYPE
○	Regular Paper
○	Comment
○	Special Section: Unmanned Aerial Vehicle-based Antenna and Field Measurements
○	Special Section: Antennas for RF Energy Harvesting and Wireless Power Transfer Applications
○	Special Section: Ultra-Wideband and Millimeter-Wave Phased-Array Antennas for Wireless Power and Data Telemetry towards Next-Generation Autonomous Systems
○	Special Section: Sub-THz and THz Radio Propagation: Measurements and Characterization
○	Special Section: Advances in Antenna Design for Metaverse and Other Modern Smart Mobile Devices
○	Special Section: Advances in Additive Manufacturing & 3D Printing: Novel Materials & Metamaterial Structures for Antennas and other Electromagnetic Devices

* Title

* Abstract

Write or Paste Abstract

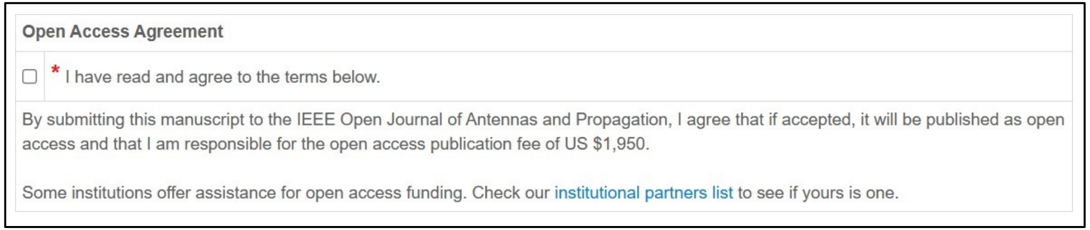
Open Access Agreement

☐ * I have read and agree to the terms below.

By submitting this manuscript to the IEEE Open Journal of Antennas and Propagation, I agree that if accepted, it will be published as open access and that I am responsible for the open access publication fee of US $1,950.

Some institutions offer assistance for open access funding. Check our institutional partners list to see if yours is one.

向 IEEE 完全 OA 期刊投稿的作者，還需接受 IEEE OA 條款和費用



Open Access Agreement

☐ * I have read and agree to the terms below.

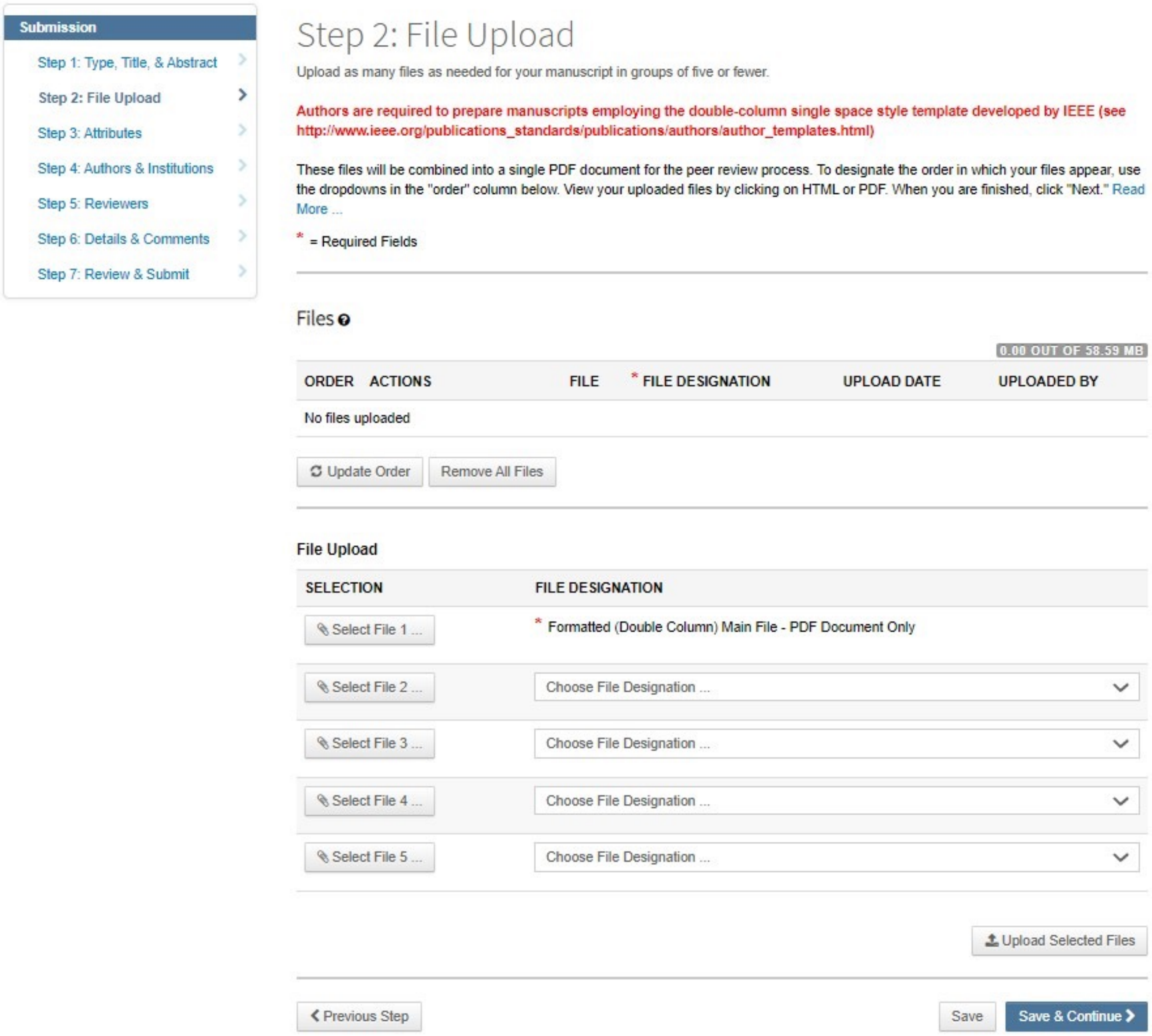
By submitting this manuscript to the IEEE Open Journal of Antennas and Propagation, I agree that if accepted, it will be published as open access and that I am responsible for the open access publication fee of US $1,950.

Some institutions offer assistance for open access funding. Check our institutional partners list to see if yours is one.

注意: 不同期刊間費用存在差異。

更多文章處理費 (APC) 相關資訊，請見：https://open.ieee.org/index.php/for-authors/article-processing-charges/.

上傳稿件



Step 2: File Upload

Upload as many files as needed for your manuscript in groups of five or fewer.

Authors are required to prepare manuscripts employing the double-column single space style template developed by IEEE (see http://www.ieee.org/publications_standards/publications/authors/author_templates.html)

These files will be combined into a single PDF document for the peer review process. To designate the order in which your files appear, use the dropdowns in the "order" column below. View your uploaded files by clicking on HTML or PDF. When you are finished, click "Next." Read More ...

* = Required Fields

Files

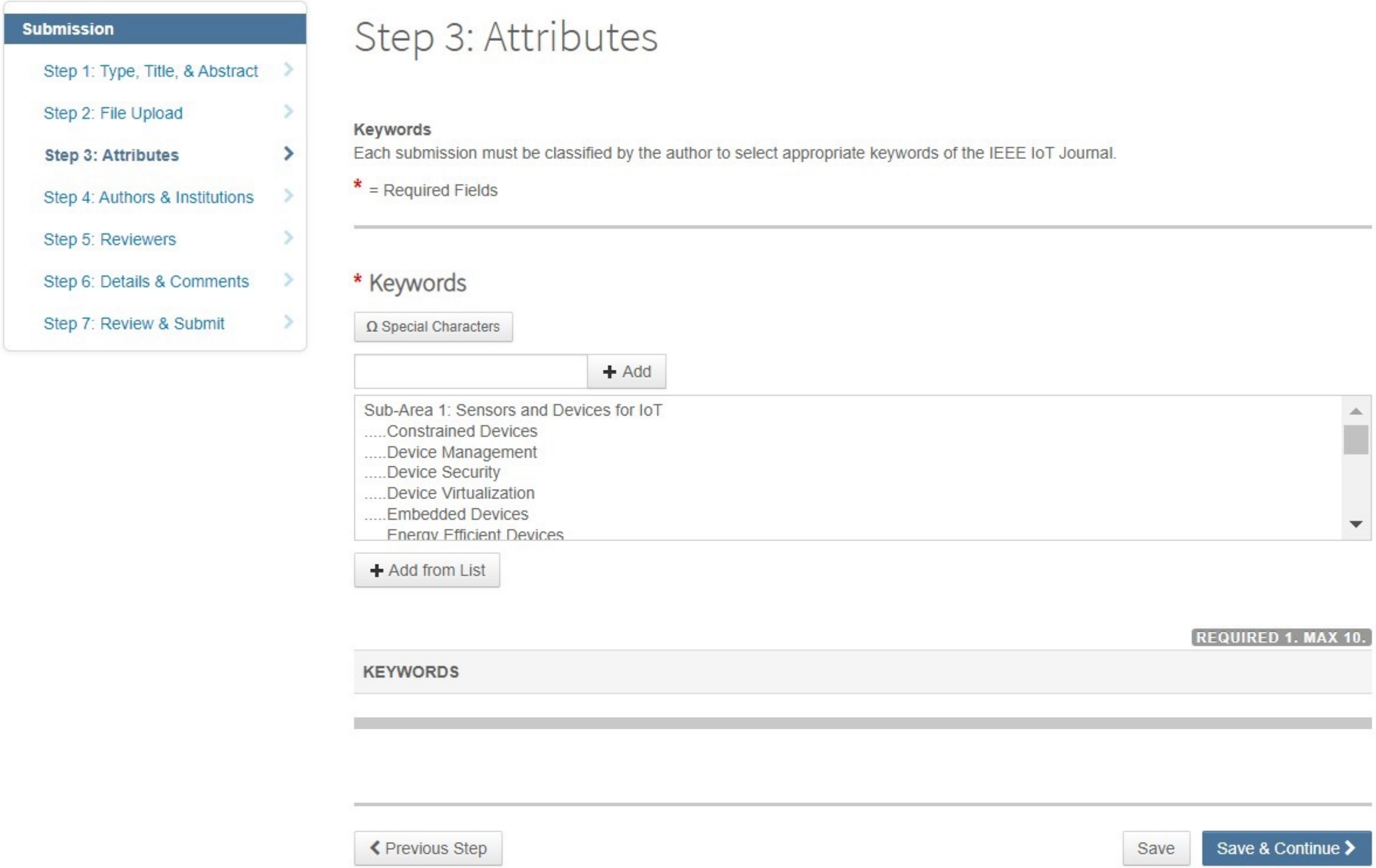
0.00 OUT OF 58.59 MB

ORDER	ACTIONS	FILE	* FILE DESIGNATION	UPLOAD DATE	UPLOADED BY
No files uploaded					

File Upload

SELECTION	FILE DESIGNATION
Select File 1 ...	* Formatted (Double Column) Main File - PDF Document Only
Select File 2 ...	Choose File Designation ...
Select File 3 ...	Choose File Designation ...
Select File 4 ...	Choose File Designation ...
Select File 5 ...	Choose File Designation ...

選擇關鍵字



Step 3: Attributes

Keywords

Each submission must be classified by the author to select appropriate keywords of the IEEE IoT Journal.

* = Required Fields

* Keywords

Sub-Area 1: Sensors and Devices for IoT
.....Constrained Devices
.....Device Management
.....Device Security
.....Device Virtualization
.....Embedded Devices
.....Energy Efficient Devices

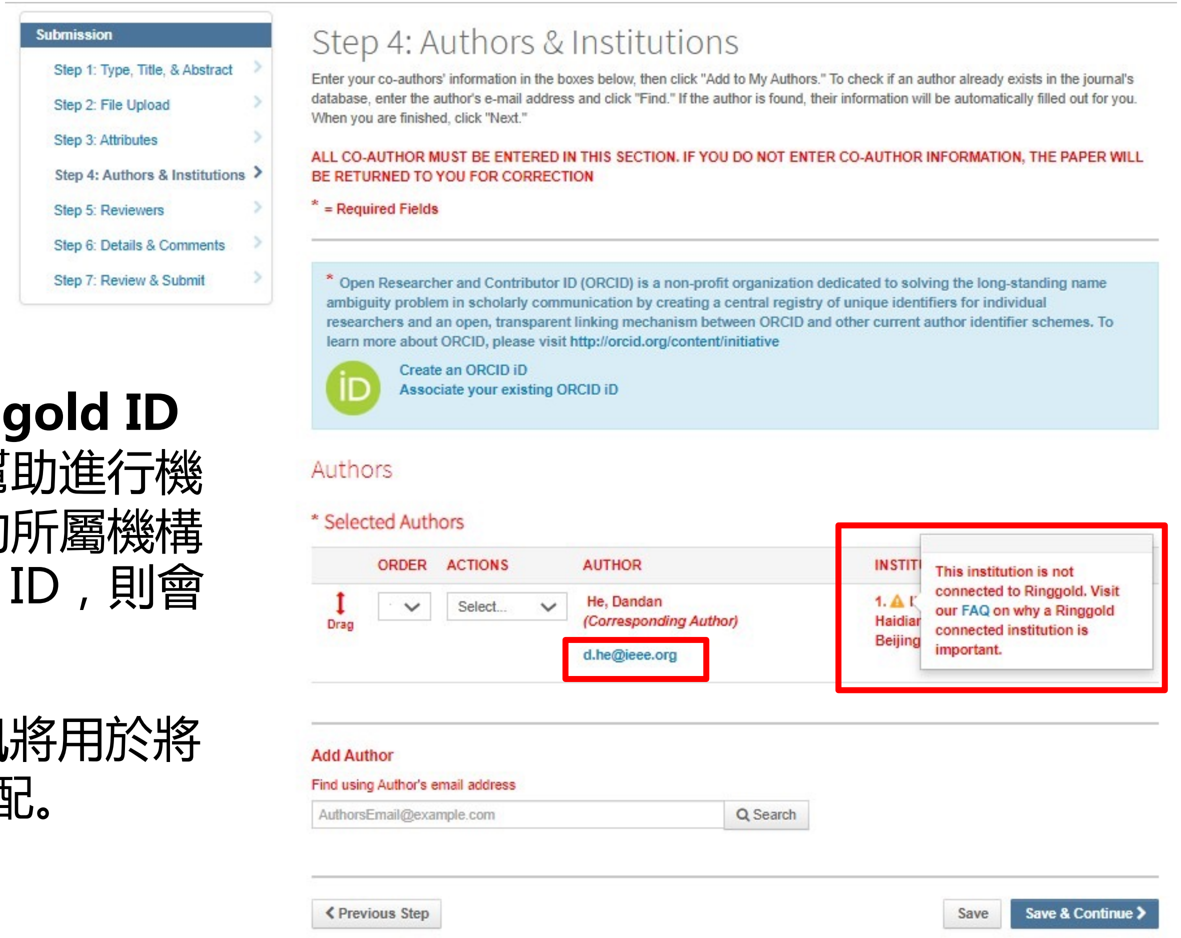
REQUIRED 1. MAX 10.

KEYWORDS

輸入作者和機構

IEEE 投稿系統中集成 **Ringgold ID**（全球機構統一身份證）幫助進行機構消歧工作。如作者輸入的所屬機構無法綁定到特定 Ringgold ID，則會顯示一條提示資訊。

此處輸入的**郵箱**與**機構資訊**將用於將作者與機構OA帳戶進行匹配。



Step 4: Authors & Institutions

Enter your co-authors' information in the boxes below, then click "Add to My Authors." To check if an author already exists in the journal's database, enter the author's e-mail address and click "Find." If the author is found, their information will be automatically filled out for you. When you are finished, click "Next."

ALL CO-AUTHOR MUST BE ENTERED IN THIS SECTION. IF YOU DO NOT ENTER CO-AUTHOR INFORMATION, THE PAPER WILL BE RETURNED TO YOU FOR CORRECTION

* = Required Fields

* Open Researcher and Contributor ID (ORCID) is a non-profit organization dedicated to solving the long-standing name ambiguity problem in scholarly communication by creating a central registry of unique identifiers for individual researchers and an open, transparent linking mechanism between ORCID and other current author identifier schemes. To learn more about ORCID, please visit http://orcid.org/content/initiative

Authors

* Selected Authors

He, Dandan
(Corresponding Author)
d.he@ieee.org

1. ⚠ I
Haidiar
Beijing

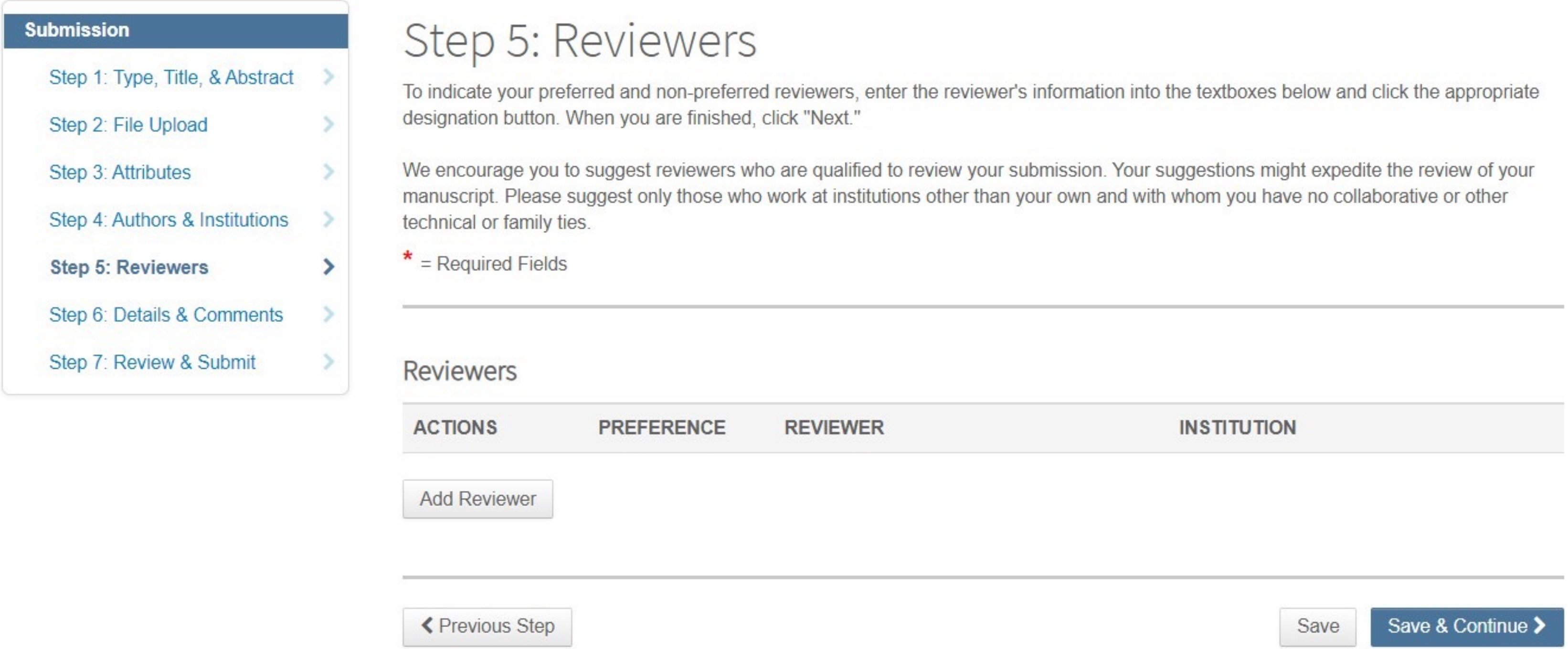
This institution is not connected to Ringgold. Visit our FAQ on why a Ringgold connected institution is important.

Add Author

Find using Author's email address

AuthorsEmail@example.com

推薦審稿人



Submission

- Step 1: Type, Title, & Abstract
- Step 2: File Upload
- Step 3: Attributes
- Step 4: Authors & Institutions
- **Step 5: Reviewers**
- Step 6: Details & Comments
- Step 7: Review & Submit

Step 5: Reviewers

To indicate your preferred and non-preferred reviewers, enter the reviewer's information into the textboxes below and click the appropriate designation button. When you are finished, click "Next."

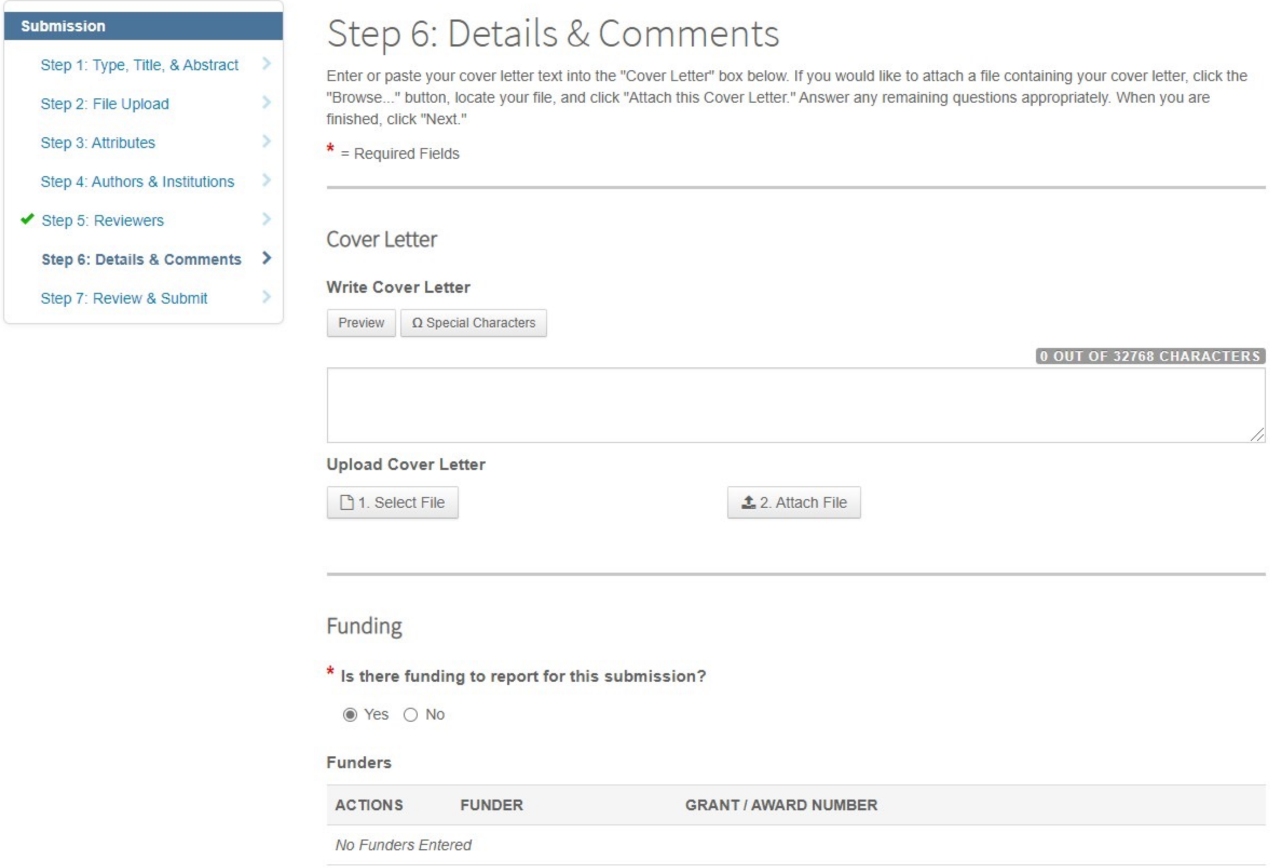
We encourage you to suggest reviewers who are qualified to review your submission. Your suggestions might expedite the review of your manuscript. Please suggest only those who work at institutions other than your own and with whom you have no collaborative or other technical or family ties.

* = Required Fields

Reviewers

ACTIONS	PREFERENCE	REVIEWER	INSTITUTION

說明信與支撐材料



Step 6: Details & Comments

Enter or paste your cover letter text into the "Cover Letter" box below. If you would like to attach a file containing your cover letter, click the "Browse..." button, locate your file, and click "Attach this Cover Letter." Answer any remaining questions appropriately. When you are finished, click "Next."

* = Required Fields

Cover Letter

Write Cover Letter

Upload Cover Letter

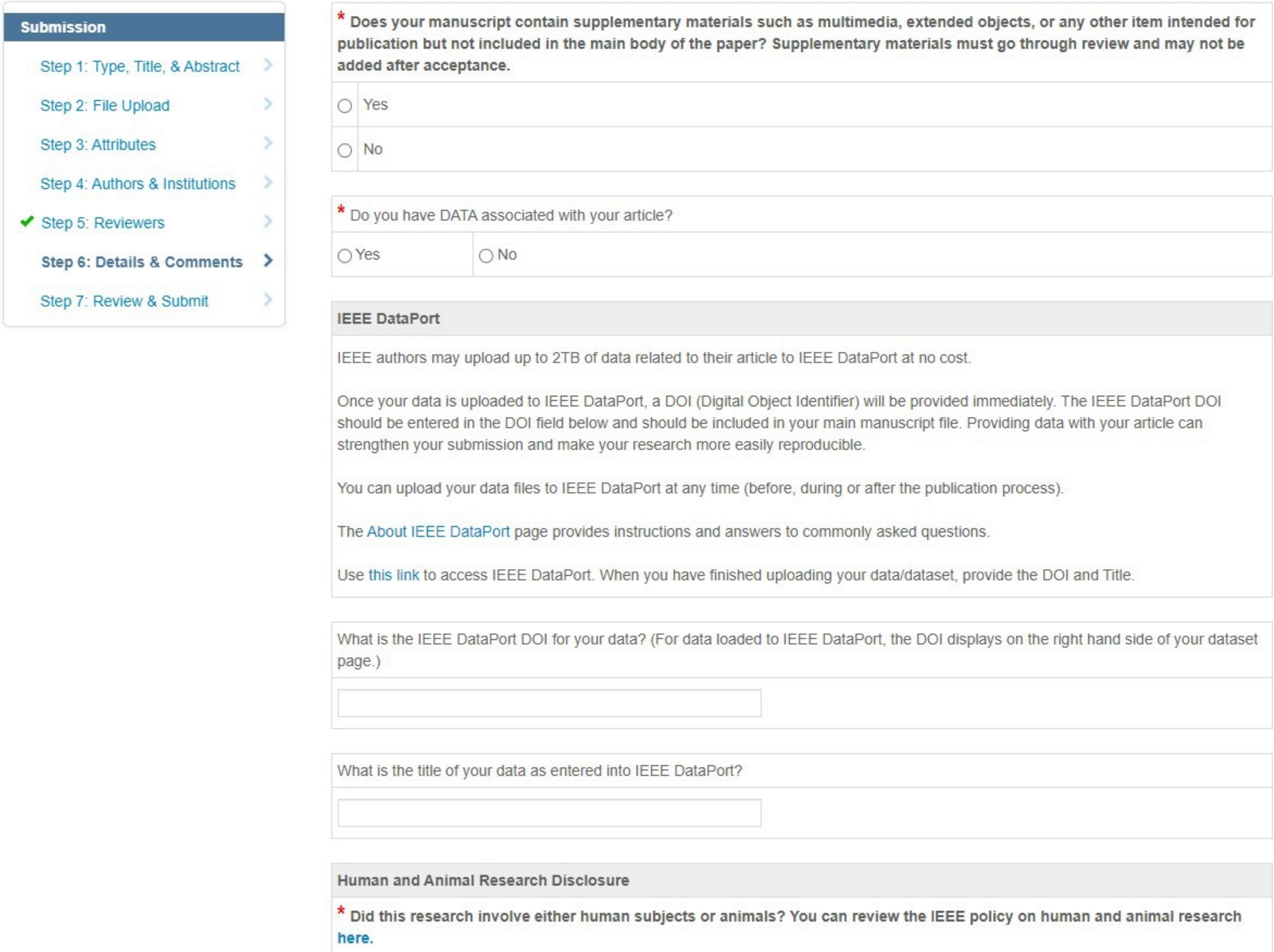
Funding

* **Is there funding to report for this submission?**

● Yes ○ No

Funders

ACTIONS	FUNDER	GRANT / AWARD NUMBER
No Funders Entered		



Submission

- Step 1: Type, Title, & Abstract
- Step 2: File Upload
- Step 3: Attributes
- Step 4: Authors & Institutions
- ✓ Step 5: Reviewers
- **Step 6: Details & Comments**
- Step 7: Review & Submit

*** Does your manuscript contain supplementary materials such as multimedia, extended objects, or any other item intended for publication but not included in the main body of the paper? Supplementary materials must go through review and may not be added after acceptance.**

○ Yes

○ No

* Do you have DATA associated with your article?

○ Yes ○ No

IEEE DataPort

IEEE authors may upload up to 2TB of data related to their article to IEEE DataPort at no cost.

Once your data is uploaded to IEEE DataPort, a DOI (Digital Object Identifier) will be provided immediately. The IEEE DataPort DOI should be entered in the DOI field below and should be included in your main manuscript file. Providing data with your article can strengthen your submission and make your research more easily reproducible.

You can upload your data files to IEEE DataPort at any time (before, during or after the publication process).

The About IEEE DataPort page provides instructions and answers to commonly asked questions.

Use this link to access IEEE DataPort. When you have finished uploading your data/dataset, provide the DOI and Title.

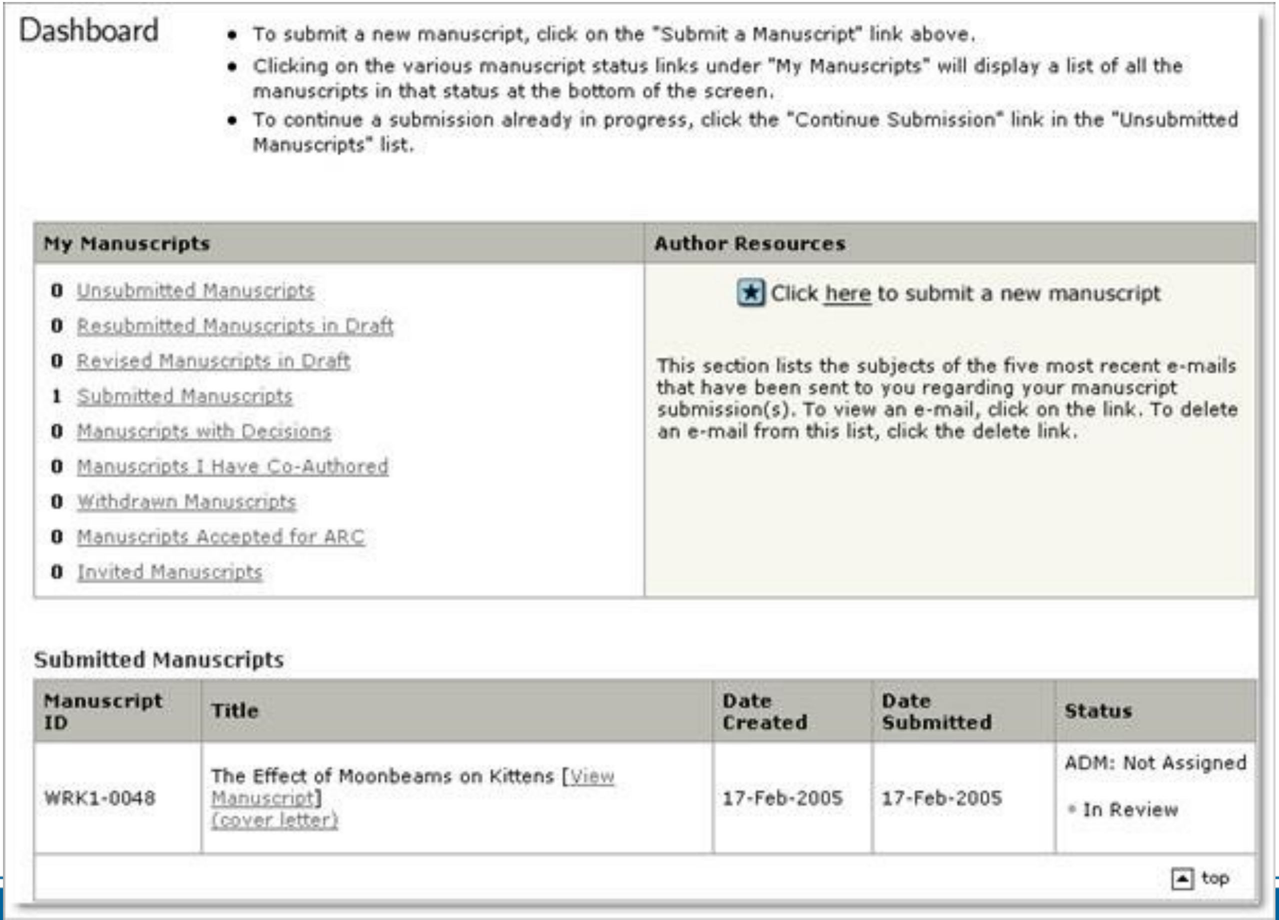
What is the IEEE DataPort DOI for your data? (For data loaded to IEEE DataPort, the DOI displays on the right hand side of your dataset page.)

What is the title of your data as entered into IEEE DataPort?

Human and Animal Research Disclosure

*** Did this research involve either human subjects or animals? You can review the IEEE policy on human and animal research here.**

查看進程



Dashboard

- To submit a new manuscript, click on the "Submit a Manuscript" link above.
- Clicking on the various manuscript status links under "My Manuscripts" will display a list of all the manuscripts in that status at the bottom of the screen.
- To continue a submission already in progress, click the "Continue Submission" link in the "Unsubmitted Manuscripts" list.

My Manuscripts	Author Resources
0 Unsubmitted Manuscripts **0** Resubmitted Manuscripts in Draft **0** Revised Manuscripts in Draft **1** Submitted Manuscripts **0** Manuscripts with Decisions **0** Manuscripts I Have Co-Authored **0** Withdrawn Manuscripts **0** Manuscripts Accepted for ARC **0** Invited Manuscripts	★ Click here to submit a new manuscript This section lists the subjects of the five most recent e-mails that have been sent to you regarding your manuscript submission(s). To view an e-mail, click on the link. To delete an e-mail from this list, click the delete link.

Submitted Manuscripts

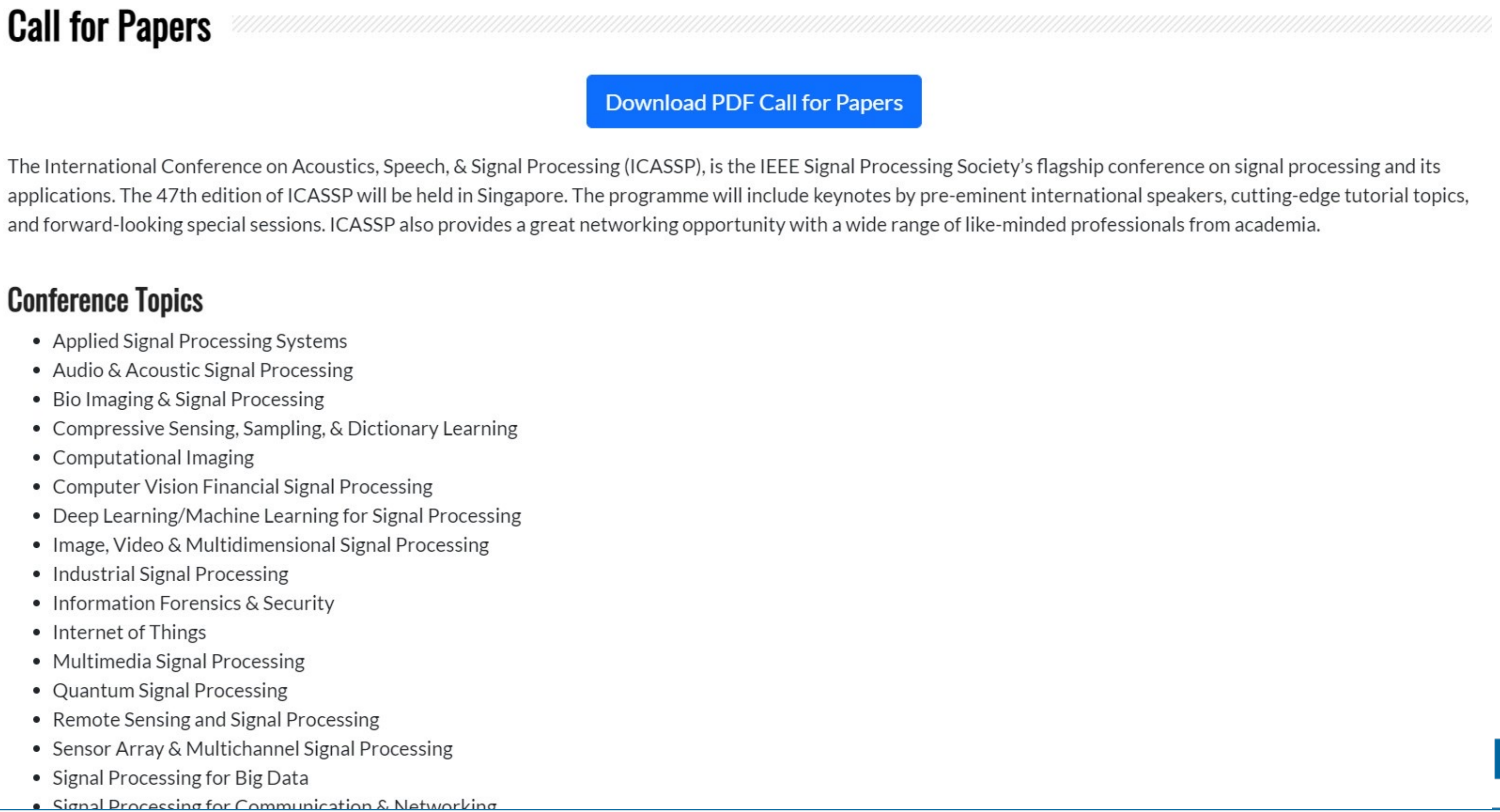
Manuscript ID	Title	Date Created	Date Submitted	Status
WRK1-0048	The Effect of Moonbeams on Kittens [View Manuscript] (cover letter)	17-Feb-2005	17-Feb-2005	ADM: Not Assigned • In Review

會議投稿流程

ICASSP 2022

2022 IEEE International Conference on Acoustics, Speech and Signal Processing, 22-27 May 2022, Singapore

會議投稿流程



Call for Papers

The International Conference on Acoustics, Speech, & Signal Processing (ICASSP), is the IEEE Signal Processing Society's flagship conference on signal processing and its applications. The 47th edition of ICASSP will be held in Singapore. The programme will include keynotes by pre-eminent international speakers, cutting-edge tutorial topics, and forward-looking special sessions. ICASSP also provides a great networking opportunity with a wide range of like-minded professionals from academia.

Conference Topics

- Applied Signal Processing Systems
- Audio & Acoustic Signal Processing
- Bio Imaging & Signal Processing
- Compressive Sensing, Sampling, & Dictionary Learning
- Computational Imaging
- Computer Vision Financial Signal Processing
- Deep Learning/Machine Learning for Signal Processing
- Image, Video & Multidimensional Signal Processing
- Industrial Signal Processing
- Information Forensics & Security
- Internet of Things
- Multimedia Signal Processing
- Quantum Signal Processing
- Remote Sensing and Signal Processing
- Sensor Array & Multichannel Signal Processing
- Signal Processing for Big Data
- Signal Processing for Communication & Networking

會議投稿流程

ICASSP 2022

2022 IEEE International Conference on Acoustics, Speech and Signal Processing, 22-27 May 2022, Singapore

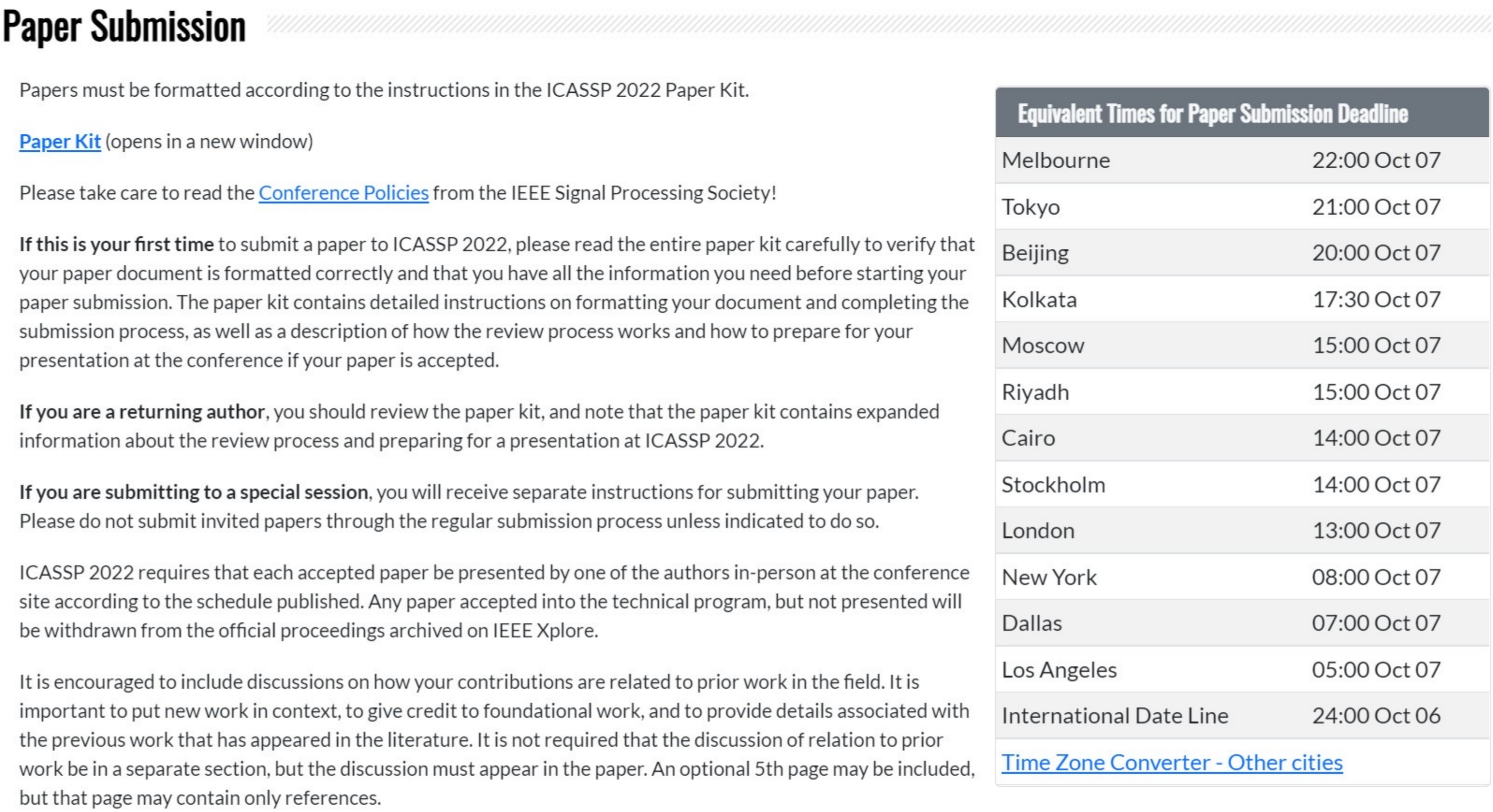
Welcome to ICASSP 2022

會議投稿流程

Important Dates

Special Session Proposal Submission	August 15, 2021
Special Session Acceptance Notification	September 06, 2021
Tutorial Proposals Deadline	October 11, 2021
Full Paper Submission Deadline	~~October 01~~ October 06, 2021
Grand Challenge Proposal Submission	October 18, 2021
Grand Challenge Acceptance Notification	November 08, 2021
Tutorial Acceptance Notification	November 15, 2021
SPS Journal Papers and Letters Due	January 10, 2022
Paper Acceptance Notification	January 21, 2022
Final Paper Submission	February 16, 2022
Author Registration Deadline	February 16, 2022
Open Preview	April 22 – May 27, 2022
Show & Tell Proposals	March 07, 2022

會議投稿流程



Paper Submission

Papers must be formatted according to the instructions in the ICASSP 2022 Paper Kit.

Paper Kit (opens in a new window)

Please take care to read the Conference Policies from the IEEE Signal Processing Society!

If this is your first time to submit a paper to ICASSP 2022, please read the entire paper kit carefully to verify that your paper document is formatted correctly and that you have all the information you need before starting your paper submission. The paper kit contains detailed instructions on formatting your document and completing the submission process, as well as a description of how the review process works and how to prepare for your presentation at the conference if your paper is accepted.

If you are a returning author, you should review the paper kit, and note that the paper kit contains expanded information about the review process and preparing for a presentation at ICASSP 2022.

If you are submitting to a special session, you will receive separate instructions for submitting your paper. Please do not submit invited papers through the regular submission process unless indicated to do so.

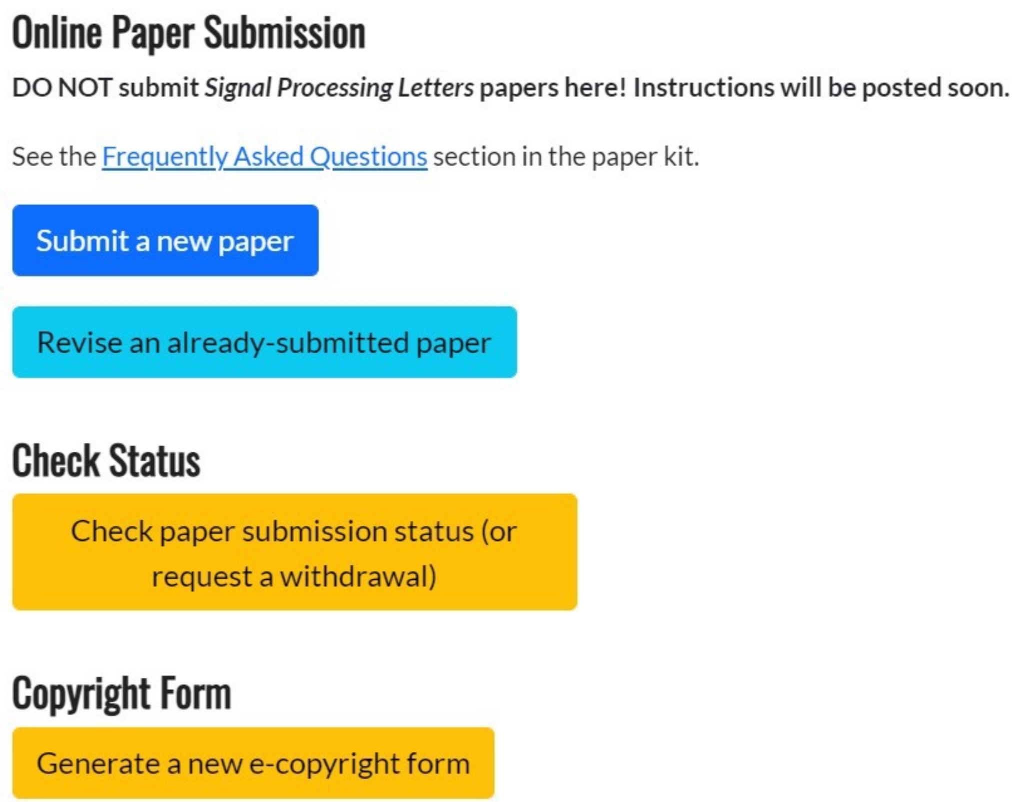
ICASSP 2022 requires that each accepted paper be presented by one of the authors in-person at the conference site according to the schedule published. Any paper accepted into the technical program, but not presented will be withdrawn from the official proceedings archived on IEEE Xplore.

It is encouraged to include discussions on how your contributions are related to prior work in the field. It is important to put new work in context, to give credit to foundational work, and to provide details associated with the previous work that has appeared in the literature. It is not required that the discussion of relation to prior work be in a separate section, but the discussion must appear in the paper. An optional 5th page may be included, but that page may contain only references.

Equivalent Times for Paper Submission Deadline	
Melbourne	22:00 Oct 07
Tokyo	21:00 Oct 07
Beijing	20:00 Oct 07
Kolkata	17:30 Oct 07
Moscow	15:00 Oct 07
Riyadh	15:00 Oct 07
Cairo	14:00 Oct 07
Stockholm	14:00 Oct 07
London	13:00 Oct 07
New York	08:00 Oct 07
Dallas	07:00 Oct 07
Los Angeles	05:00 Oct 07
International Date Line	24:00 Oct 06

Time Zone Converter - Other cities

會議投稿流程



Online Paper Submission

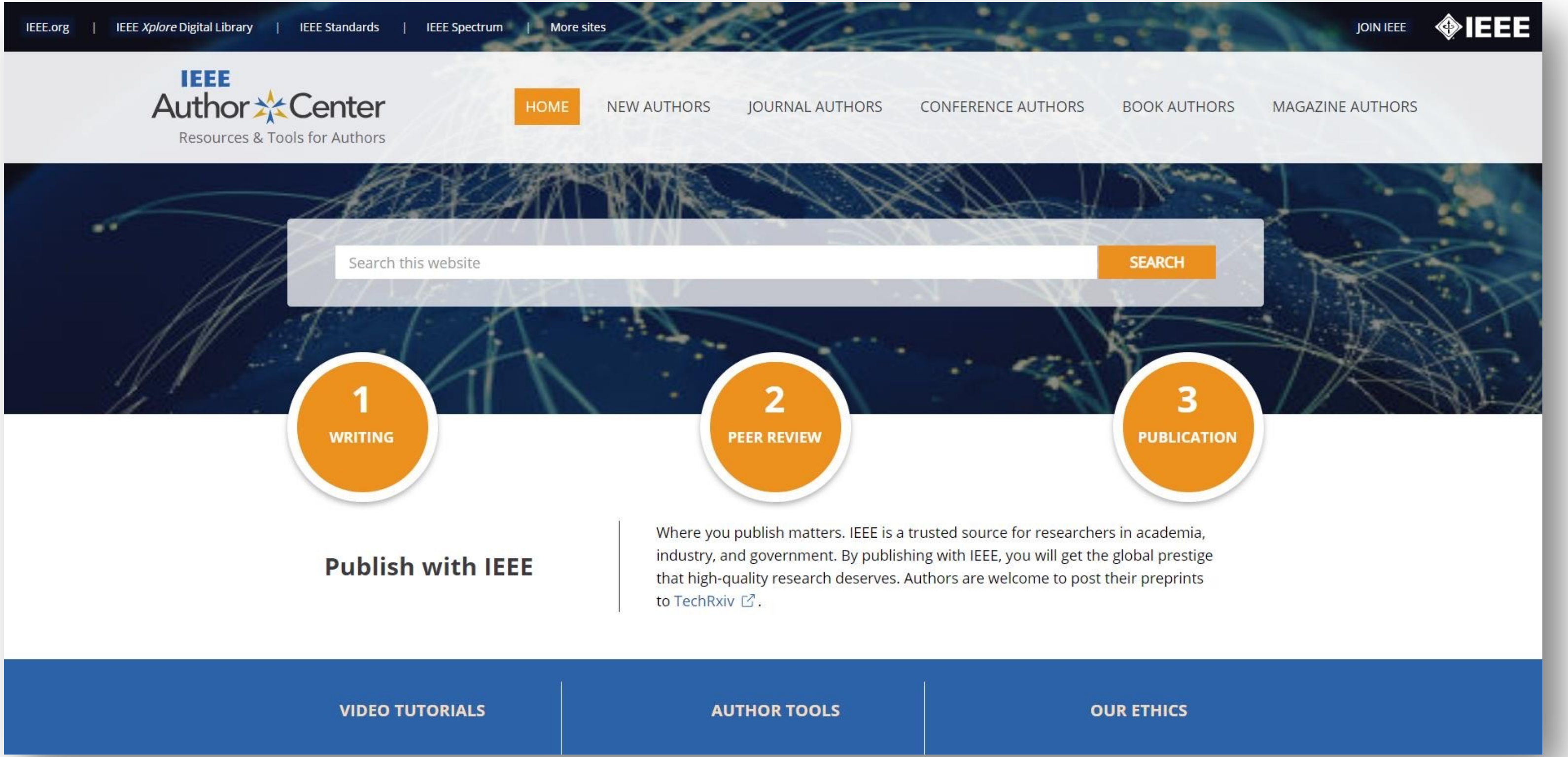
DO NOT submit *Signal Processing Letters* papers here! Instructions will be posted soon.

See the Frequently Asked Questions section in the paper kit.

Check Status

Copyright Form

作者中心與作者工具

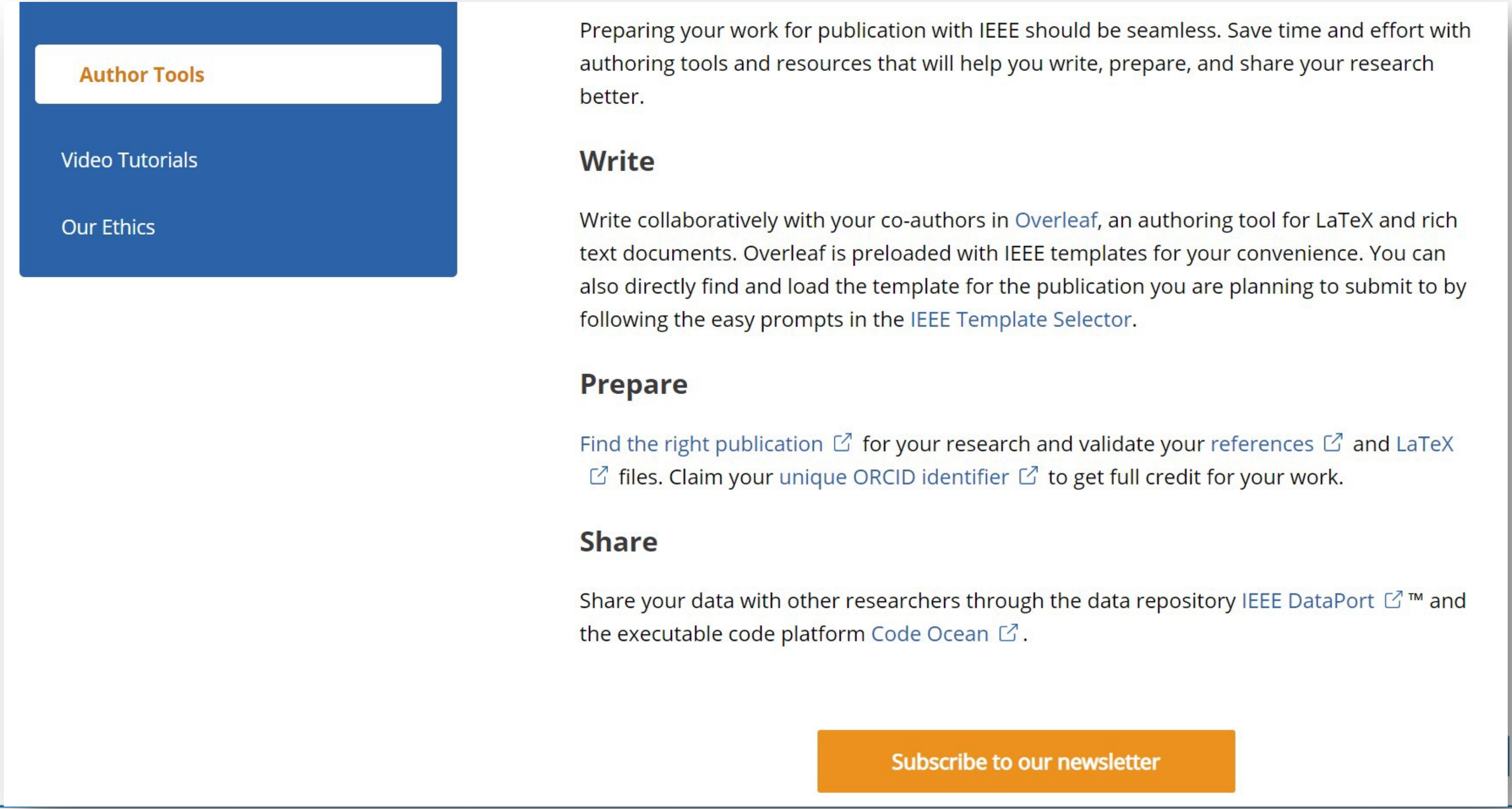


Publish with IEEE

Where you publish matters. IEEE is a trusted source for researchers in academia, industry, and government. By publishing with IEEE, you will get the global prestige that high-quality research deserves. Authors are welcome to post their preprints to TechRxiv.

https://ieeeauthorcenter.ieee.org/

作者中心與作者工具



Preparing your work for publication with IEEE should be seamless. Save time and effort with authoring tools and resources that will help you write, prepare, and share your research better.

Write

Write collaboratively with your co-authors in Overleaf, an authoring tool for LaTeX and rich text documents. Overleaf is preloaded with IEEE templates for your convenience. You can also directly find and load the template for the publication you are planning to submit to by following the easy prompts in the IEEE Template Selector.

Prepare

Find the right publication for your research and validate your references and LaTeX files. Claim your unique ORCID identifier to get full credit for your work.

Share

Share your data with other researchers through the data repository IEEE DataPort ™ and the executable code platform Code Ocean.

Prediction Using Knowledge Growing System: A Cognitive Artificial Intelligence Approach

Publisher: IEEE

Arwin Datumaya Wahyudi Sumari ; Rosa Andrie Asmara ; Dimas Rossiawan Hendra Put... **All Authors**

1 Paper Citation

401 Full Text Views

Request permission for reuse.

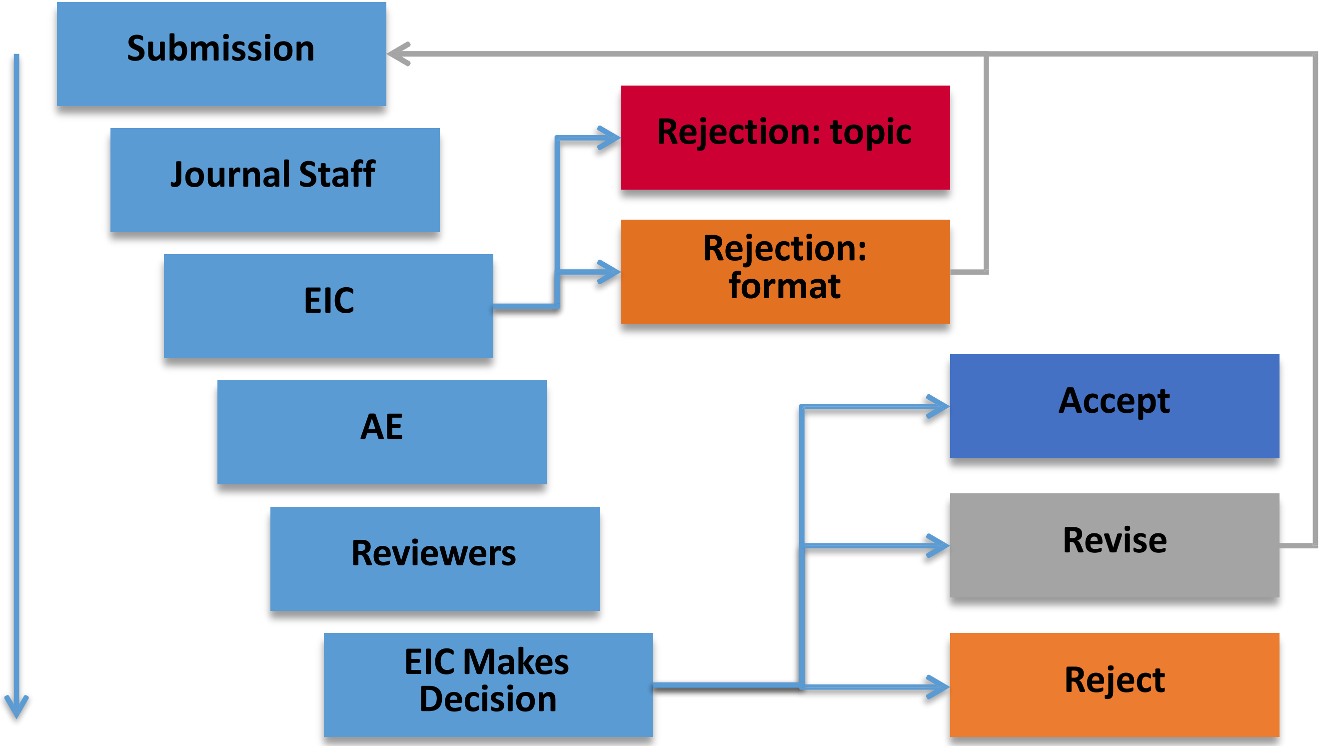
Abstract:
In the Artificial Intelligence (AI) world, prediction is a means for recognizing a phenomenon. Three approaches have been used for this task, namely supervised, semi-supervised, and unsupervised. Data annotation or labeling is

學術道德

- Authorship (and Acknowledgements) 作者與致謝
- Multiple Authors 多作者
- Plagiarism 剽竊
- Duplicate Submission 重複投稿、一稿多投
- Reuse of Published Materials 已出版材料的再使用
- Fabrication or Falsification 學術造假

編輯和審稿人在尋找什麼

評審流程 Review Process


Submission

Journal Staff

EIC

AE

Reviewers

EIC Makes Decision

Rejection: topic

Rejection: format

Accept

Revise

Reject

IEEE 編輯和評審人在尋找什麼

- Content that is appropriate, in scope and level, for the journal
- 内容符合期刊收錄範圍
- Clearly written original material that addresses a new and important problem
- 清晰表達原創研究，解決全新重要問題
- Valid methods and rationale　　有效的方法
- Conclusions that make sense　　有意義的結論
- Illustrations, tables and graphs that support the text
- 圖表圖像有力支援文字描述
- References that are current and relevant to the subject
- 能反映最近研究進展的相關參考文獻

IEEE編輯和評審人拒稿原因

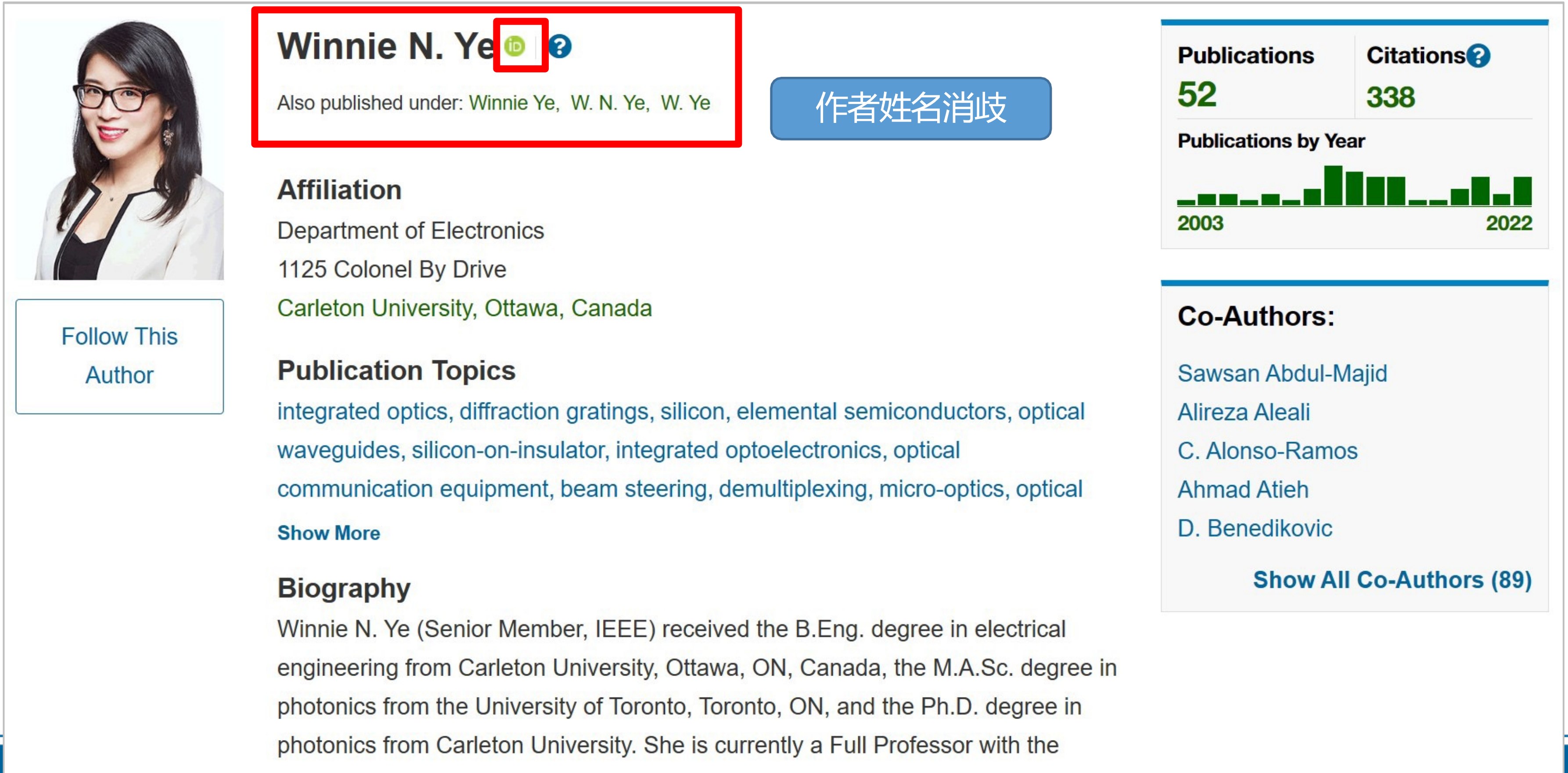
- The content is not a good fit for the publication (out-of-scope). 內容不適合該期刊
- There are serious scientific flaws: 嚴重的科學缺陷
- Inconclusive results or incorrect interpretation 無法信服的結果或不正確的解釋
  - Fraudulent research 學術造假
  - It is poorly written. 文筆差
- It does not address a big enough problem or advance the scientific field. 沒有解決重大問題或提升當前科技水準
- The work was previously published (high similarity score). 研究之前已經出版過
- The quality is not good enough for the journal. 品質沒有達到期刊要求
  - Examples of poor quality: high similarity score, short-length, aesthetics (poor presentation or writing), lack of mathematics and figures
- Reviewers have misunderstood the article. 評審人誤解文章

如何提高研究的可見度和影響力

在科研全流程提升研究可見度

- 清晰簡潔的標題，突出讀者可能的興趣點
- 精准、標準化的關鍵字
- 建立自己的學術檔案（IEEE Xplore作者頁面, ORCID等）
- 將論文提交給有影響力的學術機構發表
- 參加學術會議/研討會展示研究成果
- 多途徑推廣學術成果
- 以OA形式發表研究成果
- 分享研究相關程式碼、資料等相關材料

IEEE Xplore 作者頁面



作者姓名消歧

Winnie N. Ye

Also published under: Winnie Ye, W. N. Ye, W. Ye

Affiliation

Department of Electronics
1125 Colonel By Drive
Carleton University, Ottawa, Canada

Publication Topics

integrated optics, diffraction gratings, silicon, elemental semiconductors, optical waveguides, silicon-on-insulator, integrated optoelectronics, optical communication equipment, beam steering, demultiplexing, micro-optics, optical

Biography

Winnie N. Ye (Senior Member, IEEE) received the B.Eng. degree in electrical engineering from Carleton University, Ottawa, ON, Canada, the M.A.Sc. degree in photonics from the University of Toronto, Toronto, ON, and the Ph.D. degree in photonics from Carleton University. She is currently a Full Professor with the

Publications	Citations
52	338

Publications by Year

Co-Authors:

Sawsan Abdul-Majid
Alireza Aleali
C. Alonso-Ramos
Ahmad Atieh
D. Benedikovic

作用：

a. 連結其他平臺的作者發文，建立學術作品檔案
b. ID數位用於區分同名同姓作者
c. 在IEEE發文

https://orcid.org/
0000-0003-2817-4531

這是您嗎？登入以開始編輯

名稱
Winnie N. Ye

其他 ID
ResearcherID: E-1651-2011

活動

受邀職位與傑出貢獻 (1)

Engineering Institute of Canada (EIC): Ottawa, CA-ON, CA

2020-01-01 至 當前 | Fellow EIC
受邀職位

來源：: Winnie N. Ye

成果 (50)

Circular Optical Phased Array with Large Steering Range and High Resolution

Sensors
2022-08-16 | 雜誌文章
DOI: 10.3390/s22166135
投稿人: Daniel Benedikovič; Qiankun Liu; Alejandro Sánchez-Postigo; Ahmad Atieh; Tom Smy; Pavel Cheben; Winnie N. Ye

來源：: Crossref ★ 偏好源 (/ 2)

向IEEE期刊投稿需提交ORCID

Step 4: Authors & Institutions

Enter your co-authors' information in the boxes below, then click "Add to My Authors." To check if an author already exists in the journal's database, enter the author's e-mail address and click "Find." If the author is found, their information will be automatically filled out for you. When you are finished, click "Next."

* = Required Fields

* **Open Researcher and Contributor ID (ORCID)** is a non-profit organization dedicated to solving the long-standing name ambiguity problem in scholarly communication by creating a central registry of unique identifiers for individual researchers and an open, transparent linking mechanism between ORCID and other current author identifier schemes. To learn more about ORCID, please visit http://orcid.org/content/initiative

Authors

* Selected Authors

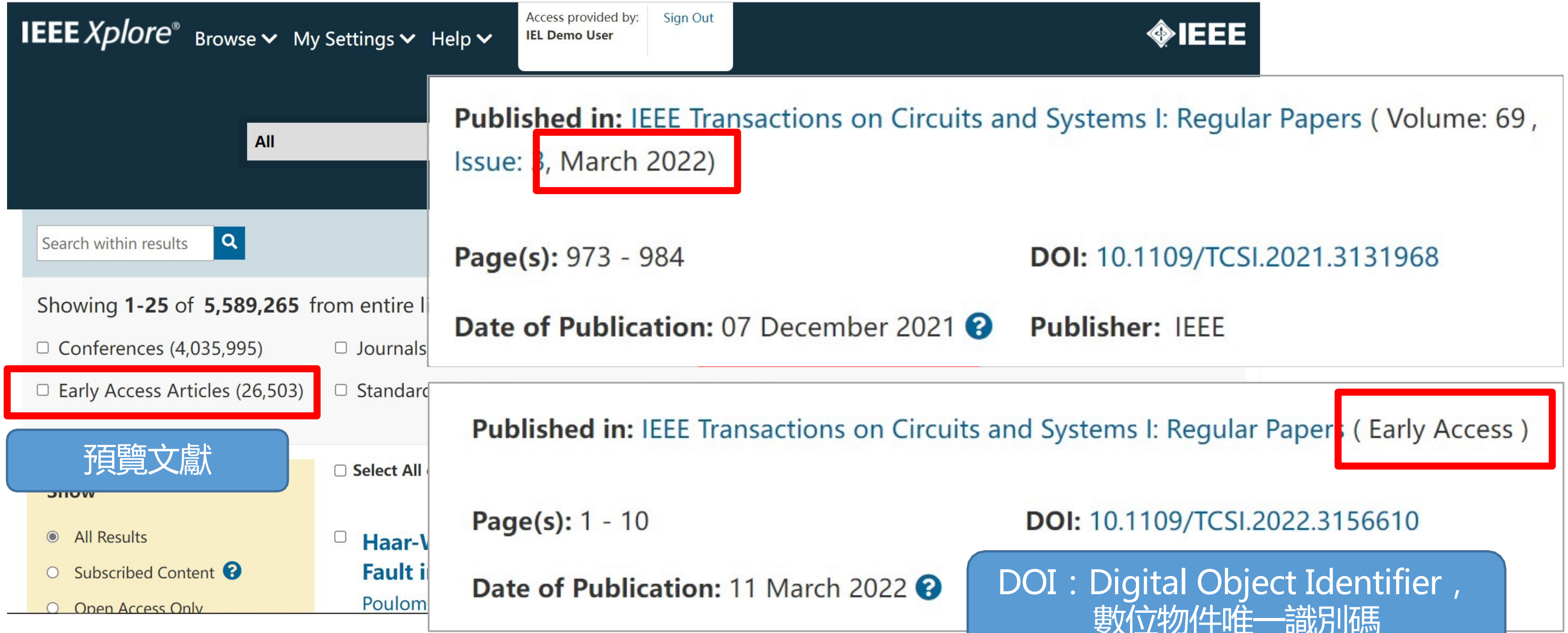
ORDER	ACTIONS	AUTHOR	INSTITUTION

- 將 ORCID 添加到您的郵件簽名、簡歷和個人主頁上
- 在提交論文和申請資金時使用ORCID

將論文提交給有影響力的學術機構發表

- 出版相關領域高品質的的期刊會議，受到同行廣泛關注
- 及時規範化的線上出版，內容永久保存與可見
- 與眾多文摘索引和發現服務供應商合作，加強研究可發現性

以預覽文獻形式快速發表經過同行評審的論文，並立即獲得DOI



Showing **1-25** of **5,589,265** from entire l

☐ Conferences (4,035,995) ☐ Journals

☐ Early Access Articles (26,503) ☐ Standard

● All Results

☐ **Haar-V**
Fault i
Poulom

Published in: IEEE Transactions on Circuits and Systems I: Regular Papers (Volume: 69 , Issue: 3, March 2022)

Page(s): 973 - 984

DOI: 10.1109/TCSI.2021.3131968

Date of Publication: 07 December 2021

Publisher: IEEE

Published in: IEEE Transactions on Circuits and Systems I: Regular Papers (Early Access)

Page(s): 1 - 10

DOI: 10.1109/TCSI.2022.3156610

Date of Publication: 11 March 2022

預覽文獻

DOI：Digital Object Identifier，
數位物件唯一識別碼

IEEE Xplore與合作夥伴，共同增強研究可見性

Clarivate
Web of Science™

Google Scholar

Scopus

NATIONAL LIBRARY OF MEDICINE

IEEE Xplore®
Digital Library

ProQuest

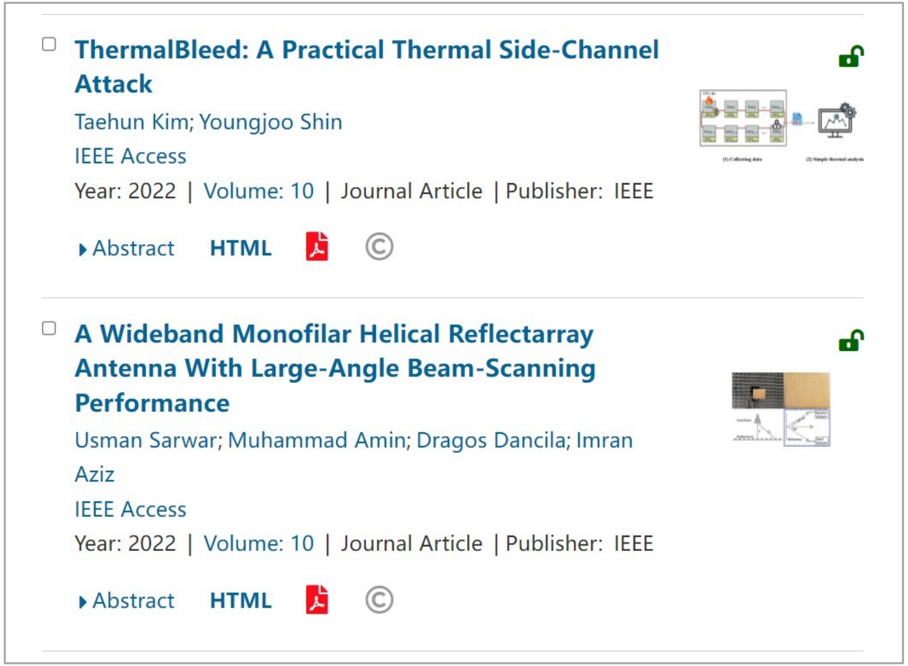
WorldCat®
Discovery Services

EBSCO

IET Inspec

多途徑推廣學術成果

- 添加摘要圖片/視頻，在檢索結果中更加矚目



☐ **ThermalBleed: A Practical Thermal Side-Channel Attack**

Taehun Kim; Youngjoo Shin

IEEE Access

Year: 2022 | Volume: 10 | Journal Article | Publisher: IEEE

☐ **A Wideband Monofilar Helical Reflectarray Antenna With Large-Angle Beam-Scanning Performance**

Usman Sarwar; Muhammad Amin; Dragos Dancila; Imran Aziz

IEEE Access

Year: 2022 | Volume: 10 | Journal Article | Publisher: IEEE

Published in: IEEE Access (Volume: 9)

Page(s): 83740 - 83750

INSPEC Accession Number: 21012216

Date of Publication: 02 June 2021

DOI: 10.1109/ACCESS.2021.3085404

Electronic ISSN: 2169-3536

Publisher: IEEE

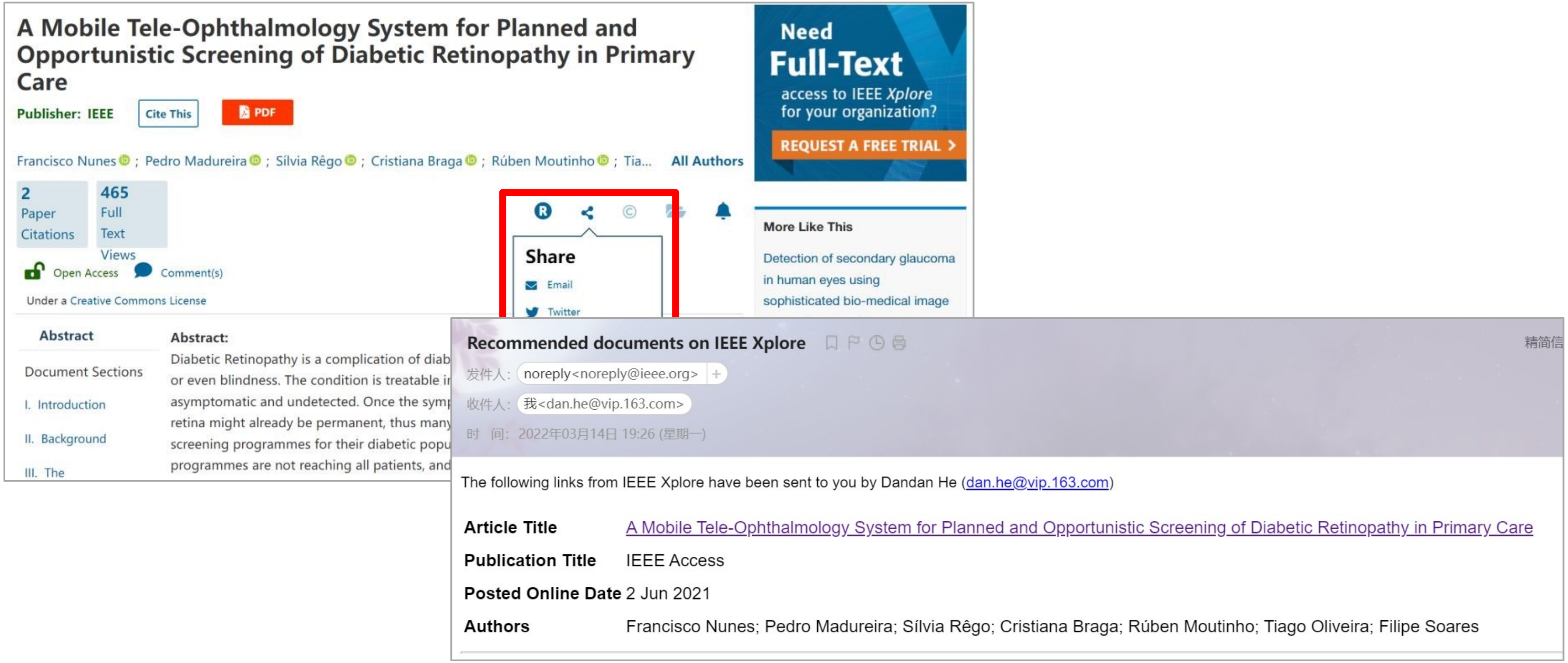
Funding Agency:

Architecture of the EyeFundusScopeNEO system.

https://ieeeaccess.ieee.org/about-ieee-access/announcements/enter-the-best-video-award-for-the-opportunity-to-win-500/

多途徑推廣學術成果

- 通過郵件/社交媒體等形式分享學術成果



A Mobile Tele-Ophthalmology System for Planned and Opportunistic Screening of Diabetic Retinopathy in Primary Care

Publisher: IEEE

Francisco Nunes ; Pedro Madureira ; Sílvia Rêgo ; Cristiana Braga ; Rúben Moutinho ; Tia... **All Authors**

2 Paper Citations

465 Full Text Views

Open Access

Comment(s)

Under a Creative Commons License

Abstract:

Diabetic Retinopathy is a complication of diab
or even blindness. The condition is treatable i
asymptomatic and undetected. Once the symp
retina might already be permanent, thus many
screening programmes for their diabetic popu
programmes are not reaching all patients, and

Need Full-Text access to IEEE *Xplore* for your organization?

More Like This

Detection of secondary glaucoma in human eyes using sophisticated bio-medical image

Recommended documents on IEEE Xplore

发件人：noreply<noreply@ieee.org>

收件人：我<dan.he@vip.163.com>

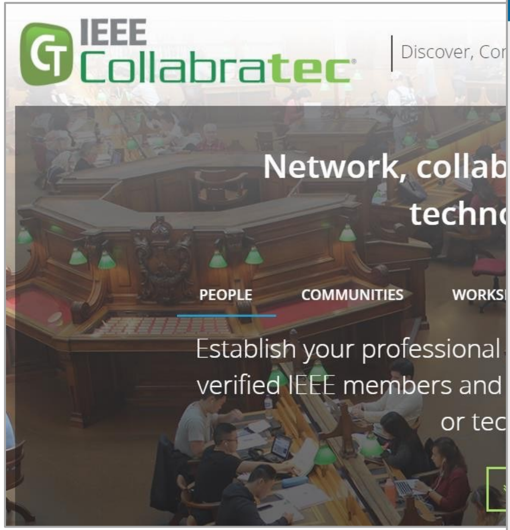
时　间：2022年03月14日 19:26 (星期一)

The following links from IEEE Xplore have been sent to you by Dandan He (dan.he@vip.163.com)

Article Title	A Mobile Tele-Ophthalmology System for Planned and Opportunistic Screening of Diabetic Retinopathy in Primary Care
Publication Title	IEEE Access
Posted Online Date	2 Jun 2021
Authors	Francisco Nunes; Pedro Madureira; Sílvia Rêgo; Cristiana Braga; Rúben Moutinho; Tiago Oliveira; Filipe Soares

多途徑推廣學術成果

- 利用科研社交工具



IEEE Collabratec

Discover, Co

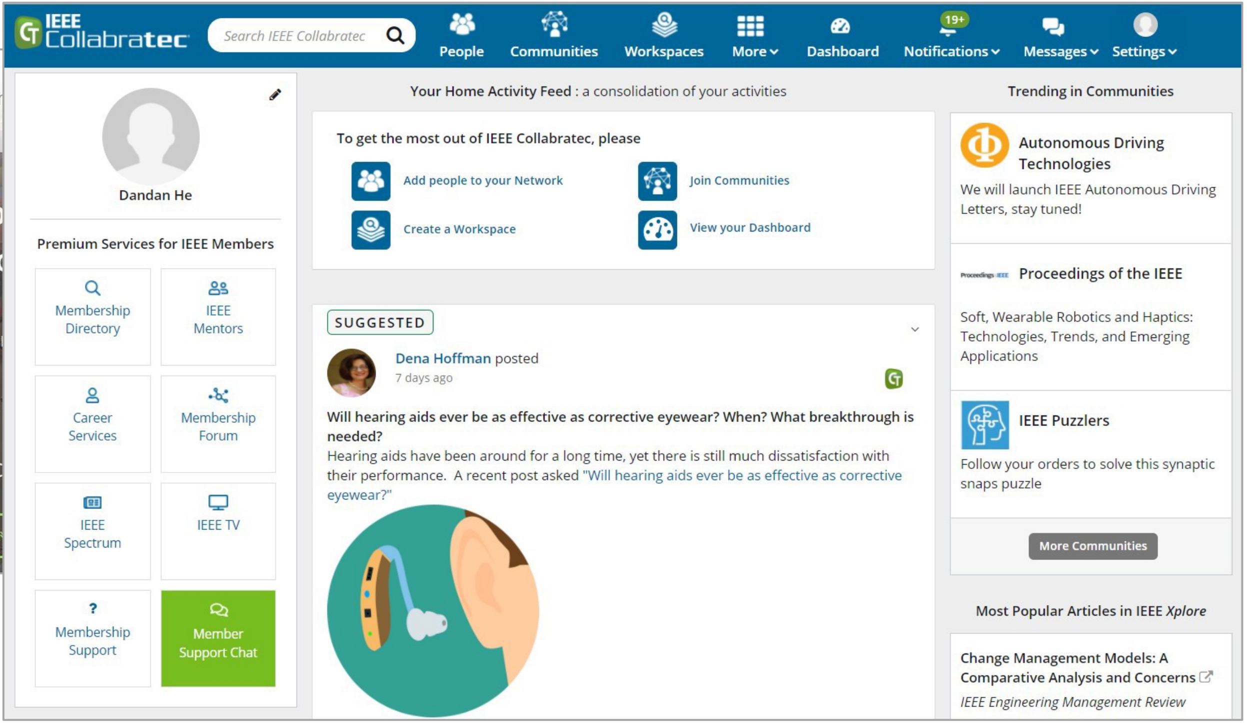
Network, collab

techn

Establish your professional

verified IEEE members and

or tec



Dandan He

Premium Services for IEEE Members

Your Home Activity Feed : a consolidation of your activities

To get the most out of IEEE Collabratec, please

SUGGESTED

Dena Hoffman posted

7 days ago

Will hearing aids ever be as effective as corrective eyewear? When? What breakthrough is needed?

Hearing aids have been around for a long time, yet there is still much dissatisfaction with their performance. A recent post asked "Will hearing aids ever be as effective as corrective eyewear?"

Trending in Communities

Autonomous Driving Technologies

We will launch IEEE Autonomous Driving Letters, stay tuned!

Proceedings of the IEEE

Soft, Wearable Robotics and Haptics: Technologies, Trends, and Emerging Applications

IEEE Puzzlers

Follow your orders to solve this synaptic snaps puzzle

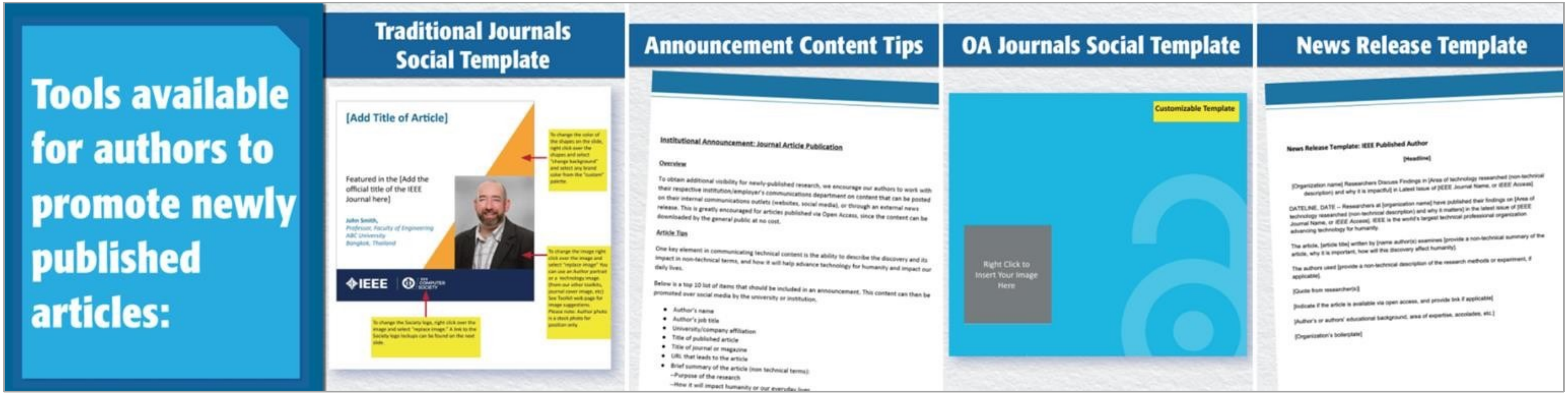
Most Popular Articles in IEEE *Xplore*

Change Management Models: A Comparative Analysis and Concerns

IEEE Engineering Management Review

多途徑推廣學術成果

- 便於在社群媒體上分享的範本工具包



Tools available for authors to promote newly published articles:

Traditional Journals Social Template

[Add Title of Article]

Featured in the [Add the official title of the IEEE Journal here]

John Smith,
Professor, Faculty of Engineering
ABC University
Bangkok, Thailand

Announcement Content Tips

Institutional Announcement: Journal Article Publication

Overview

To obtain additional visibility for newly-published research, we encourage our authors to work with their respective institution/employer's communications department on content that can be posted on their internal communications outlets (websites, social media), or through an external news release. This is greatly encouraged for articles published via Open Access, since the content can be downloaded by the general public at no cost.

Article Tips

One key element in communicating technical content is the ability to describe the discovery and its impact in non-technical terms, and how it will help advance technology for humanity and impact our daily lives.

Below is a top 10 list of items that should be included in an announcement. This content can than be promoted over social media by the university or institution.

- Author's name
- Author's job title
- University/company affiliation
- Title of published article
- Title of journal or magazine
- URL that leads to the article
- Brief summary of the article (non technical terms):
  --Purpose of the research
  --How it will impact humanity or our everyday lives

OA Journals Social Template

Customizable Template

Right Click to Insert Your Image Here

News Release Template

News Release Template: IEEE Published Author

[Headline]

[Organization name] Researchers Discuss Findings in [Area of technology researched (non-technical description) and why it is impactful] in Latest Issue of [IEEE Journal Name, or IEEE Access]

DATELINE, DATE -- Researchers at [organization name] have published their findings on [Area of technology researched (non-technical description) and why it matters] in the latest issue of [IEEE Journal Name, or IEEE Access]. IEEE is the world's largest technical professional organization advancing technology for humanity.

The article, [article title] written by [name author(s)] examines [provide a non-technical summary of the article, why it is important, how will this discovery affect humanity].

The authors used [provide a non-technical description of the research methods or experiment, if applicable].

[Quote from researcher(s)]

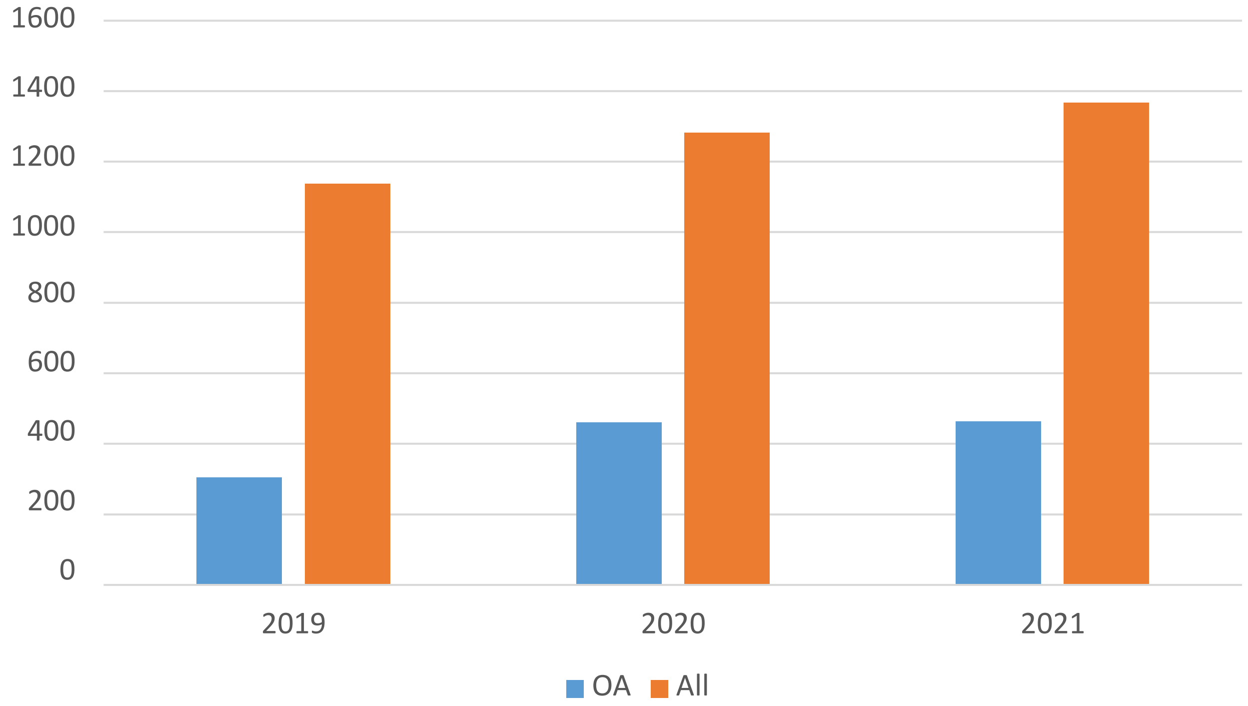
[Indicate if the article is available via open access, and provide link if applicable]

[Author's or authors' educational background, area of expertise, accolades, etc.]

[Organization's boilerplate]

https://brand-experience.ieee.org/toolkits/ieee-social-media-and-communications-toolkit-for-authors/

臺灣通訊作者 IEEE 發文趨勢



2022 Top OA Titles in Taiwan

Ranking	OA Journal Title
1	IEEE Access
2	IEEE Journal of the Electron Devices Society
3	IEEE Photonics Journal
4	IEEE Transactions on Neural Systems and Rehabilitation Engineering
5	IEEE Journal of Translational Engineering in Health & Medicine

什麼是開放取用（Open Access, OA）

- 文章在出版後免費提供，無需訂閱付費
- 通常由作者或研究資助機構支付文章處理費 (APC)
- 可能包括與傳統出版物不同的版權或授權合約

Gold OA - 金色開放取用

Green OA - 綠色開放取用

什麼是掠奪性（predatory）期刊?

掠奪性出版是一種剝削性出版商業模式，涉及向作者收取出版費，很少進行或沒有同行評審，製作品質差且難以找到。

警惕！
- 不專業的網站
- 誘人的緊急提交邀請
- 不尋常的收稿範圍
- 缺乏引用指標

如何規避掠奪性期刊

https://thinkchecksubmit.org

- 您或您的同事知道該期刊嗎？
  - 您以前讀過該期刊上的文章嗎？
  - 在期刊上發現最新論文容易嗎？
- 您能否輕鬆識別並聯繫出版商？
  - 出版商名稱是否清楚地顯示在期刊網站上？
  - 您可以通過電話、電子郵件和郵寄方式聯繫出版商嗎？
- 期刊是否清楚顯示其使用的同行評審類型？
- 文章是否在您使用的服務中編入索引？
- 是否明確收取哪些費用？
  - 期刊網站是否解釋了費用明細以及何時收取？
- 你瞭解編委會嗎？
  - 你聽說過編委會成員嗎？
  - 編委成員本人是否提及過該刊
- 出版商是公認的行業領軍者嗎？

THINK CHECK SUBMIT

Choose the right journal or publisher for your research

For More: https://innovate.ieee.org/beware-of-predatory-journals/

為什麼要關注OA?

- 在更廣泛讀者間傳播科研成果
- 有利於同行在自己研究的基礎上推進領域進步
- 符合資助機構對OA出版的要求

IEEE出版在訂閱期刊和開放取用期刊兩方面均不斷發展。IEEE持續提供更多選擇來支援全球作者的科研工作和出版需求。

在IEEE發表開放取用研究，可以為您帶來如下幫助：

- 在IEEE期刊出版，這些高品質期刊受到同行信賴，並在相關領域具有很高的被引用率
- 在IEEE Xplore數字圖書館的數百萬使用者間獲得最大的可見性和廣泛的全球影響力
- 遵循IEEE既定的出版原則和品質標準，進行嚴格的同行評審
- 快速決策，讓您的研究更快地曝光，許多期刊的審稿週期僅為幾周
- IEEE 與 Elsevier、EBSCO、OCLC、Clarivate、ProQuest、IET和NLM等文摘索引和發現服務供應商保持積極的合作夥伴關係，進一步增強作者研究的可發現性
- 與IEEE的其他開放科學解決方案集成，方便分享研究資料、代碼等其他研究材料
- 輕鬆遵循開放獲取要求

IEEE 29 種完全開放取用期刊

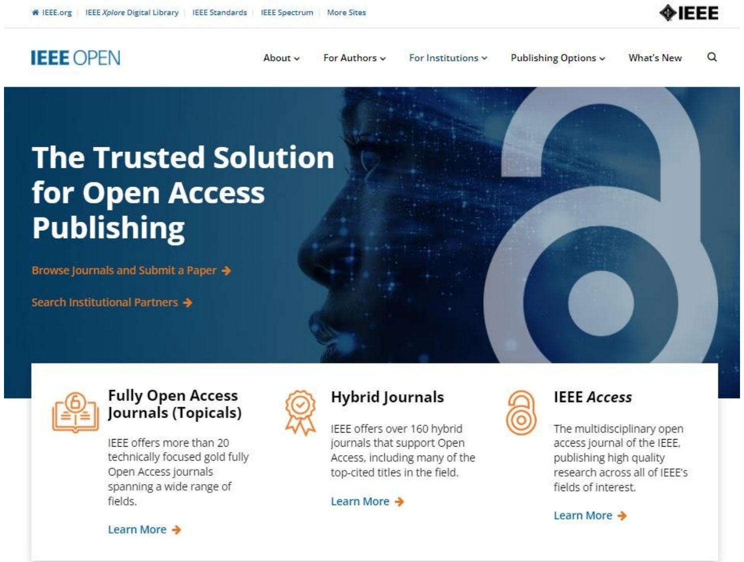
- IEEE Access
- IEEE Open Journal of Antennas and Propagation
- IEEE Journal of Selected Topics in Applied Earth Observations and Remote Sensing
- IEEE Open Journal of Circuits and Systems
- IEEE Open Journal of the Communications Society
- IEEE Open Journal of the Computer Society
- IEEE Open Journal of Control Systems
- IEEE Journal of the Electron Devices Society
- IEEE Open Journal of Engineering in Medicine and Biology
- IEEE Journal on Exploratory Solid-State Computational Devices and Circuits
- IEEE Journal of Indoor and Seamless Positioning and Navigation **NEW for 2023**
- IEEE Open Journal of the Industrial Electronics Society
- IEEE Open Journal of Industry Applications
- IEEE Open Journal of Instrumentation and Measurement
- IEEE Open Journal of Intelligent Transportation Systems
- IEEE Transactions On Machine Learning in Communications and Networking **New for 2023**
- IEEE Journal of Microwaves
- IEEE Open Journal of Nanotechnology
- IEEE Transactions on Neural Systems and Rehabilitation Engineering
- IEEE Photonics Journal
- IEEE Open Access Journal of Power and Energy
- IEEE Open Journal of Power Electronics
- IEEE Transactions on Quantum Engineering
- IEEE Open Journal of Signal Processing
- IEEE Open Journal of the Solid-State Circuits Society
- IEEE Open Journal of Systems Engineering **New for 2023**
- IEEE Journal of Translational Engineering in Health and Medicine
- IEEE Open Journal of Ultrasonics, Ferroelectrics, and Frequency Control
- IEEE Open Journal of Vehicular Technology

More information: open.ieee.org

IEEE作者OA選項

IEEE提供3種OA選擇以滿足作者不同需求

- 20多種完全開放取用專題期刊（Fully open access topical journals）
- 160多種混合期刊（Hybrid journals）
- 跨學科綜合期刊（Multidisciplinary journal）——IEEE Access


IEEE.org | IEEE *Xplore* Digital Library | IEEE Standards | IEEE Spectrum | More Sites

IEEE OPEN

About | For Authors | For Institutions | Publishing Options | What's New

The Trusted Solution for Open Access Publishing

Browse Journals and Submit a Paper →

Search Institutional Partners →

Fully Open Access Journals (Topicals)

IEEE offers more than 20 technically focused gold fully Open Access journals spanning a wide range of fields.

Learn More →

Hybrid Journals

IEEE offers over 160 hybrid journals that support Open Access, including many of the top-cited titles in the field.

Learn More →

IEEE *Access*

The multidisciplinary open access journal of the IEEE, publishing high quality research across all of IEEE's fields of interest.

Learn More →

http://open.ieee.org/

IEEE 開放科學解決方案

CODE OCEAN

TechRxiv™
Powered by IEEE

IEEE
DataPort™

開放研究中的代碼

免費上傳程式碼，
用　戶無需訂閱即
可存 取碼

FREE

開放研究預印本

在同行評議之前
發佈早期和完全
開放版本的文章

FREE

開放研究中的資料

發佈與研究相關
的大型資料集

IEEE開放取用期刊

IEEE擁有26種完全
開放取用期刊供作
者選擇

IEEE

Code Ocean

可與其他學術平臺集成的線上程式碼可再現性平臺。

- 作者可以在可運算環境發佈程式碼和演算法
- Code Ocean外掛程式直接集成在IEEE Xplore文章細節頁面
- 用戶/讀者可以基於他人發佈的程式碼進一步演算
- 用戶獲得與原始作者相同的運算環境， 無需額外設置和安裝
- 用戶可以使用一系列配套工具： Jupyter, Code versioning, collaboration, flexible computing等
- 您也可以匯出該程式碼集，在Code Ocean之外的平臺運行。 這是一個開放平臺
- 發佈的程式碼集帶有DOI，屬OA資源
- 程式碼和演算法現在可以進行同行評審

文章細節頁面

Code Ocean

Index Modulation Based Coordinate Interleaved Orthogonal Design for Secure Communications

Publisher: IEEE

Burak Ozpoyraz ; Ibrahim Yildirim ; Ertugrul Basar **All Authors**

Abstract:
In this paper, we propose a physical layer security scheme that exploits a novel index modulation (IM) technique for coordinate interleaved orthogonal designs (CIOD). Utilizing the diversity gain of CIOD transmission, the proposed scheme, named CIOD-IM, provides an improved spectral efficiency by means of IM. In order to provide a satisfactory secrecy rate, we design a particular artificial noise matrix, which does not affect the performance of the legitimate receiver, while deteriorating the performance of the eavesdropper. We derive expressions of the ergodic secrecy rate and the theoretical bit error rate upper bound. In addition, we analyze the case of imperfect channel estimation by taking practical concerns into consideration. It is shown via computer simulations that the proposed scheme outperforms the existing IM-based schemes and might be a candidate for future secure communication systems.

Code & Datasets

This article includes code hosted on Code Ocean, a computational reproducibility platform that allows users to view, modify, run, and download code included with IEEE *Xplore* articles. NOTE: A Code Ocean user account is required to access functionality in the capsule below.

Code: MATLAB Index Modulation Based Coordinate Interleaved Orthogonal Designs

Index Modulation Based Coordinate Interleaved Ort... *(Burak Özpoyraz, İbra...)*

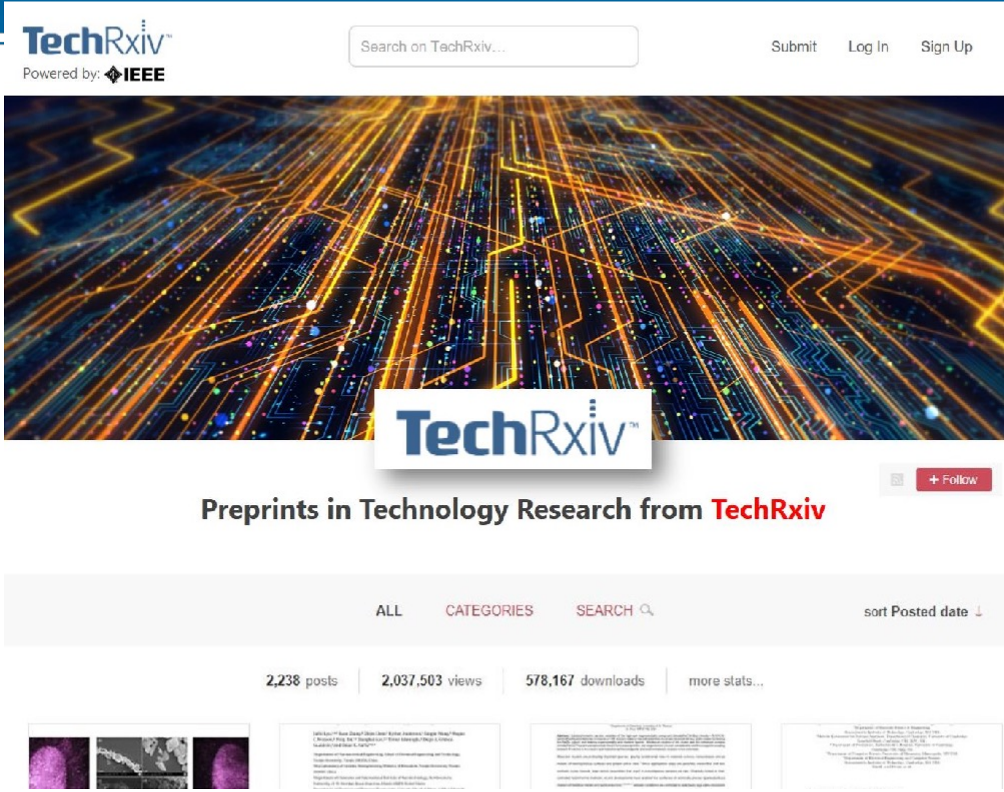
metadata	881 B
environment	199 B
code	122.61 KB
CIOD_IM_BER_Single.m	447 B
CIOD_IM_BER.m	14.53 KB
CIOD_IM_Secrecy.m	10.37 KB
CIOD_IM_TheoBER.m	8.36 KB
ConventionalBER.m	9.86 KB
ConventionalSecrecy.m	7.83 KB
EfficientAlamoutiBER.m	9.49 KB
EfficientAlamoutiSecrecy.m	6.41 KB
Figure.m	23.87 KB
FigureParfor.m	30.16 KB
LICENSE	1.04 KB
run	210 B
data	0 B
results	476 B
Figures	311.7 KB
Results	7.97 KB
README.md	127 B

```
clear all;
clc;

num_iterations = 1e4;
N = 4;
M = 4;
P_tot_des = 1;
alpha = 0.5;
sigma2 = 0;
SNRdB = 10;
mod_type = "PSK";
[BER_bob, BER_eve, error_bob, error_eve] =...
    CIOD_IM_BER(num_iterations, N, M, P_tot_des, alpha, sigma2, SNRdB, mod_type);

fprintf("Bob's BER = %1.6f\n", BER_bob);
fprintf("Eve's BER = %1.6f\n", BER_eve);
fprintf("Number of Bob's Bit Errors = %d\n", error_bob);
fprintf("Number of Eve's Bit Errors = %d\n", error_eve);
```

TechRxiv.org

一個開放的預印伺服器，用於未出版的電氣工程、電腦科學和相關技術研究。 覆蓋領域包括：

- Aerospace
- Bioengineering
- Communication, Networking and Broadcast Technologies
- Components, Circuits, Devices and Systems
- Computing and Processing
- Engineered Materials, Dielectrics and Plasmas
- Engineering Profession
- Fields, Waves and Electromagnetics
- General Topics for Engineers
- Geoscience
- Nuclear Engineering
- Photonics and Electrooptics
- Power, Energy and Industry Applications
- Robotics and Control Systems
- Signal Processing and Analysis
- Transportation



Preprints in Technology Research from TechRxiv

2,238 posts | 2,037,503 views | 578,167 downloads | more stats...

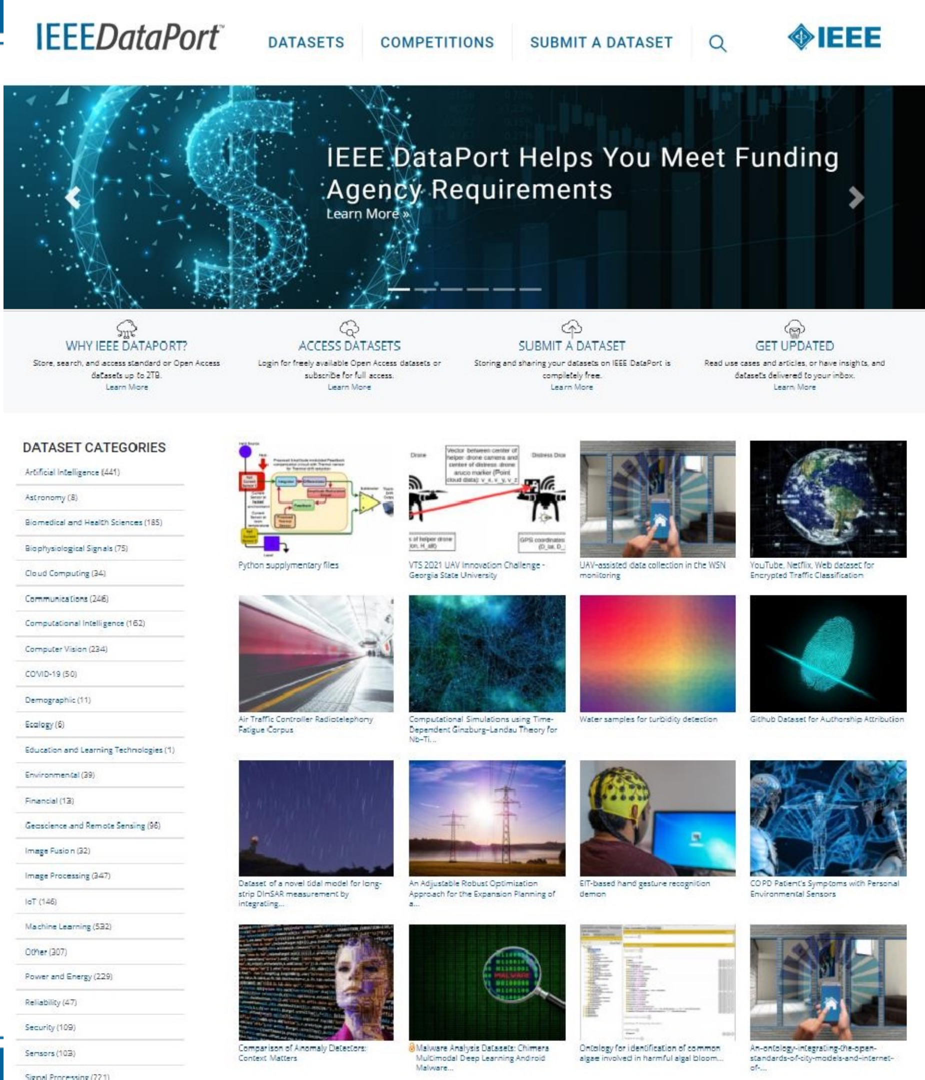
通過使用TechRxiv，作者可以迅速將其作品傳播給廣泛受眾，並獲得有關其研究草案版本的社群回饋。 “預印本”是文章的草稿版本（已發佈文章的最終版本不應提交給TechRxiv）。

IEEE Dataport

https://ieee-dataport.org/

IEEE 為滿足機構與研究人員日益增長的資料需求，開發的集資料存儲、檢索、共用、合作為一體的科研資料平臺，便於機構使用者訪問、存儲、共用以及管理研究資料，進而提升機構科研能力。

- 每個資料集可無限期存儲多個資料檔案， 個人用戶上限2TB，機構用戶上限10TB
- 資料集可以連結到Xplore文章
- 資料集帶有DOI
- 可以制定引文並以多種格式提供給用戶
- 與ORCID集成，用戶可以選擇將IEEE DataPort資料集自動添加到他們的ORCID資產列表中
- 可以存儲和連結相關文檔——腳本、視覺化文件、相關文檔，支持研究可重複性
- 獲得全球範圍的曝光



IEEE DataPort Helps You Meet Funding Agency Requirements

Learn More »

WHY IEEE DATAPORT?

Store, search, and access standard or Open Access datasets up to 2TB.

Learn More

ACCESS DATASETS

Login for freely available Open Access datasets or subscribe for full access.

Learn More

SUBMIT A DATASET

Storing and sharing your datasets on IEEE DataPort is completely free.

Learn More

GET UPDATED

Read use cases and articles, or have insights, and datasets delivered to your inbox.

Learn More

DATASET CATEGORIES

Artificial Intelligence (441)
Astronomy (8)
Biomedical and Health Sciences (185)
Biophysiological Signals (75)
Cloud Computing (34)
Communications (246)
Computational Intelligence (162)
Computer Vision (234)
COVID-19 (50)
Demographic (11)
Ecology (6)
Education and Learning Technologies (1)
Environmental (39)
Financial (13)
Geoscience and Remote Sensing (96)
Image Fusion (32)
Image Processing (347)
IoT (146)
Machine Learning (532)
Other (307)
Power and Energy (229)
Reliability (47)
Security (109)
Sensors (103)
Signal Processing (721)

Python supplymentary files

VTS 2021 UAV Innovation Challenge - Georgia State University

UAV-assisted data collection in the WSN monitoring

YouTube, Netflix, Web dataset for Encrypted Traffic Classification

Air Traffic Controller Radiotelephony Fatigue Corpus

Computational Simulations using Time-Dependent Ginzburg-Landau Theory for Nb-Ti...

Water samples for turbidity detection

Github Dataset for Authorship Attribution

Dataset of a novel tidal model for long-strip DInSAR measurement by integrating...

An Adjustable Robust Optimization Approach for the Expansion Planning of a...

EIT-based hand gesture recognition demon

COPD Patient's Symptoms with Personal Environmental Sensors

Comparison of Anomaly Detectors: Context Matters

Malware Analysis Datasets: Chimera Multimodal Deep Learning Android Malware...

Ontology for identification of common algae involved in harmful algal bloom...

An-ontology-integrating-the-open-standards-of-city-models-and-internet-of-...

IEEE 2023 OA 投稿優惠詳解與實踐流程

背景

IEEE為本輪訂購IEL資料庫的CONCERT成員學校在IEEE完全OA期刊*發表論文提供優惠：

- 1）學校**通訊作者**在**IEEE完全OA期刊**發表論文自動向機構申請使用APC Token支付
- 2）通訊作者投稿過程中，通過**機構郵箱**或**機構資訊**進行匹配
- 3）作者可以以**均一優惠價格USD1,560****使用APC Token進行支付
- 4）此優惠與其他優惠不可同時使用
- 5）Token使用申請將提交至機構管理員進行審核批復
- 6）如不希望使用此優惠，可聯繫機構管理員或 ieee_oa@hintoninfo.com 拒絕申請。待管理員拒絕後，通訊作者將收到郵件自行支付APC

* https://open.ieee.org/about/

IEEE完全OA期刊包括Fully OA Topical Journals與IEEE Access

**IEEE完全OA期刊2023標準APC為USD1,950

Open Access allows authors to publish in respected, high-quality, scholarly journals, while also complying with the latest open access policies. IEEE makes the transition simple by providing several options for authors to choose from:

- Fully Open Access Topical Journals ➔
- Hybrid Journals ➔
- IEEE *Access* (Multidisciplinary Open Access Journal) ➔

IEEE OA 優惠操作流程——作者流程

Step 1　提交稿件

SCHOLARONE™

Step 2　稿件被錄用後，簽署版權協定

IEEE

IEEE Electronic Copyright Form

Step 3　使用折扣並申請適用優惠

Copyright Clearance Center | RightsLink

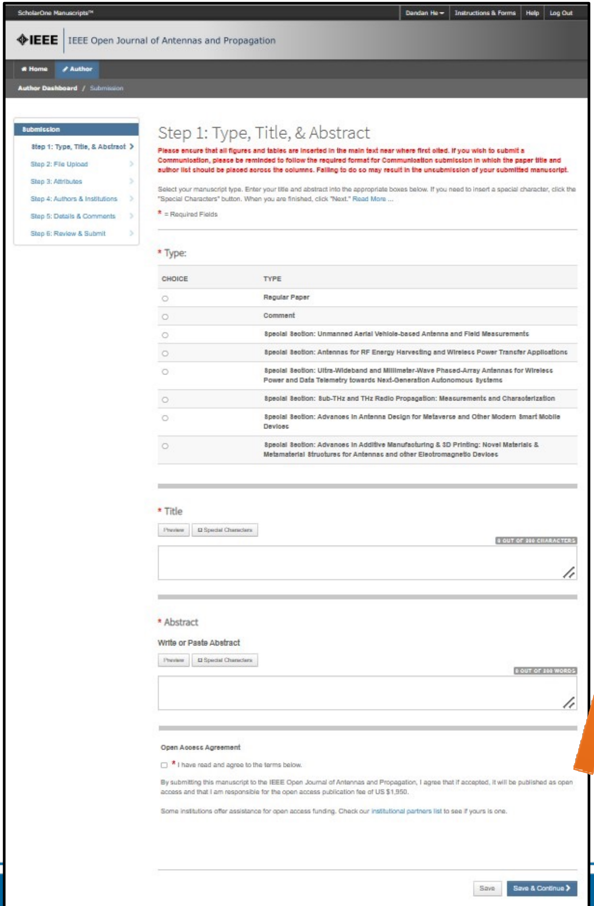
Step 4　支付 OA APC

藍新金流
NewebPay

提交稿件

- 通訊作者將完成提交稿件的過程。
- 向 IEEE 完全 OA 期刊投稿的作者，將在步驟 1 中被要求接受 IEEE OA 條款和費用

提交稿件 – 步驟 1 – 完全OA期刊



Step 1: Type, Title, & Abstract

Please ensure that all figures and tables are inserted in the main text near where first cited. If you wish to submit a Communication, please be reminded to follow the required format for Communication submission in which the paper title and author list should be placed across the columns. Failing to do so may result in the unsubmission of your submitted manuscript.

Select your manuscript type. Enter your title and abstract into the appropriate boxes below. If you need to insert a special character, click the "Special Characters" button. When you are finished, click "Next." Read More ...

* = Required Fields

* Type:

CHOICE	TYPE
○	Regular Paper
○	Comment
○	Special Section: Unmanned Aerial Vehicle-based Antenna and Field Measurements
○	Special Section: Antennas for RF Energy Harvesting and Wireless Power Transfer Applications
○	Special Section: Ultra-Wideband and Millimeter-Wave Phased-Array Antennas for Wireless Power and Data Telemetry towards Next-Generation Autonomous Systems
○	Special Section: Sub-THz and THz Radio Propagation: Measurements and Characterization
○	Special Section: Advances in Antenna Design for Metaverse and Other Modern Smart Mobile Devices
○	Special Section: Advances in Additive Manufacturing & 3D Printing: Novel Materials & Metamaterial Structures for Antennas and other Electromagnetic Devices

* Title

* Abstract

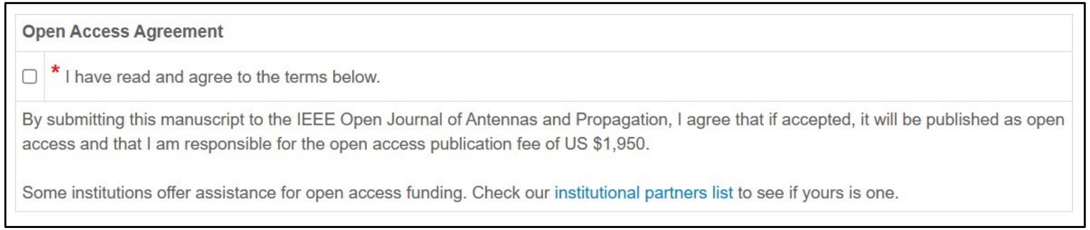
Write or Paste Abstract

Open Access Agreement

☐ * I have read and agree to the terms below.

By submitting this manuscript to the IEEE Open Journal of Antennas and Propagation, I agree that if accepted, it will be published as open access and that I am responsible for the open access publication fee of US $1,950.

Some institutions offer assistance for open access funding. Check our institutional partners list to see if yours is one.


Open Access Agreement

☐ * I have read and agree to the terms below.

By submitting this manuscript to the IEEE Open Journal of Antennas and Propagation, I agree that if accepted, it will be published as open access and that I am responsible for the open access publication fee of US $1,950.

Some institutions offer assistance for open access funding. Check our institutional partners list to see if yours is one.

注意: 不同期刊間費用存在差異。

更多文章處理費 (APC) 相關資訊，請見：
https://open.ieee.org/for-authors/article-processing-charges/

提交稿件 – 步驟 4

通訊作者為所有作者添加所屬機構資訊。

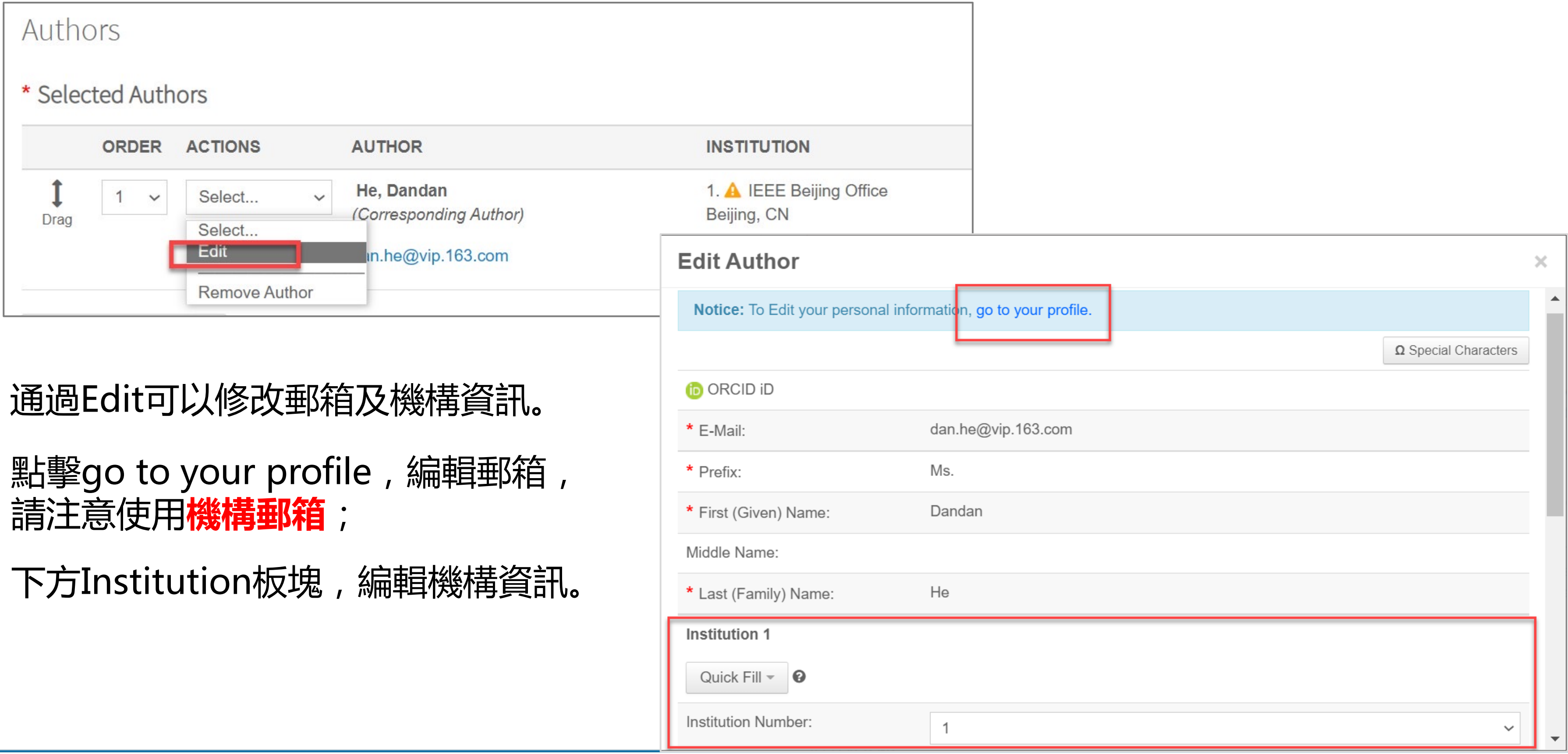
此處輸入的**郵箱**與**機構資訊**將用於將作者與機構OA帳戶進行匹配，其一匹配即可。

Authors

* Selected Authors

	ORDER	ACTIONS	AUTHOR	INSTITUTION
Drag	1	Select...	**He, Dandan** *(Corresponding Author)* dan.he@vip.163.com	1. IEEE, CSM Room 1503, South Tower, Raycom InfoTech Park C, No.2 Kexueyuan South Road, Haidian District New York, CN 10016

提交稿件 – 修改郵箱與機構資訊



Authors

* Selected Authors

ORDER	ACTIONS	AUTHOR	INSTITUTION
Drag 1	Select...	**He, Dandan** *(Corresponding Author)* n.he@vip.163.com	1. ⚠ IEEE Beijing Office Beijing, CN

Edit Author

Notice: To Edit your personal information, go to your profile.

* E-Mail: dan.he@vip.163.com

* Prefix: Ms.

* First (Given) Name: Dandan

Middle Name:

* Last (Family) Name: He

Institution 1

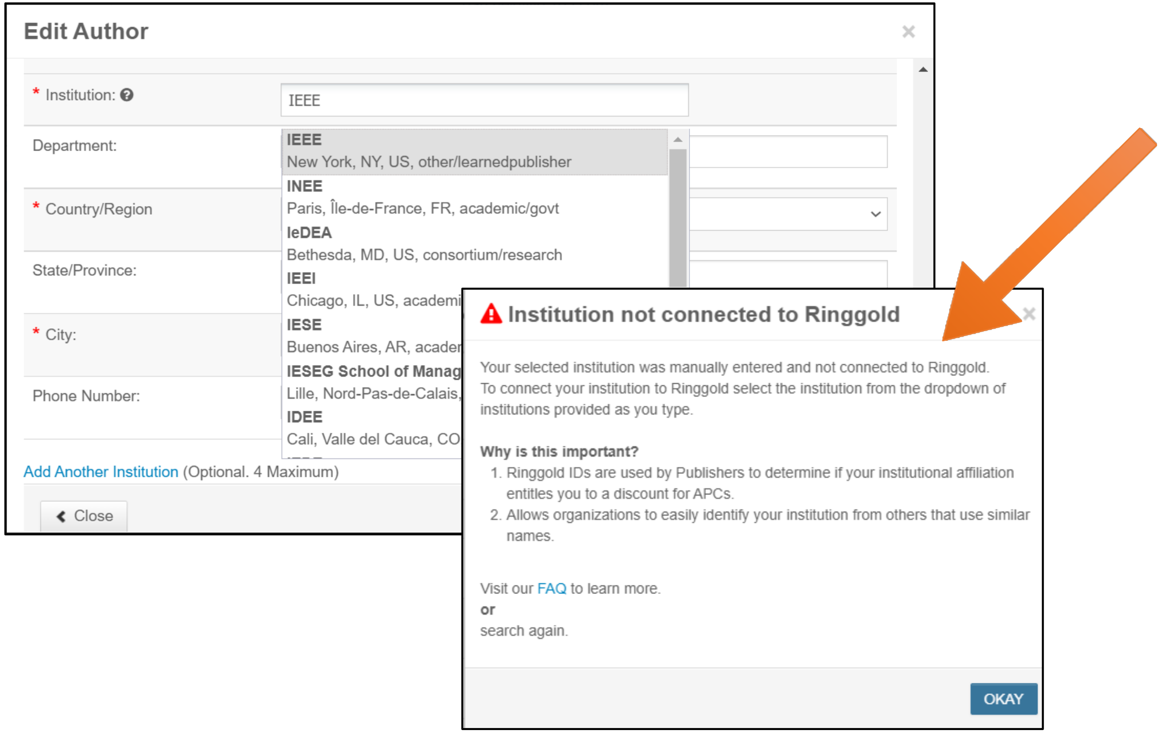
Institution Number: 1

通過Edit可以修改郵箱及機構資訊。

點擊go to your profile，編輯郵箱，請注意使用**機構郵箱**；

下方Institution板塊，編輯機構資訊。

提交稿件 – 綁定 Ringgold ID



Edit Author

* Institution: IEEE

Department:

* Country/Region

State/Province:

* City:

Phone Number:

IEEE
New York, NY, US, other/learnedpublisher
INEE
Paris, Île-de-France, FR, academic/govt
IeDEA
Bethesda, MD, US, consortium/research
IEEI
Chicago, IL, US, academi
IESE
Buenos Aires, AR, acader
IESEG School of Manag
Lille, Nord-Pas-de-Calais,
IDEE
Cali, Valle del Cauca, CO

Add Another Institution (Optional. 4 Maximum)

Institution not connected to Ringgold

Your selected institution was manually entered and not connected to Ringgold. To connect your institution to Ringgold select the institution from the dropdown of institutions provided as you type.

Why is this important?

1. Ringgold IDs are used by Publishers to determine if your institutional affiliation entitles you to a discount for APCs.
2. Allows organizations to easily identify your institution from others that use similar names.

Visit our FAQ to learn more.
or
search again.

添加作者的所屬機構資訊時，系統將向作者提供與作者輸入的內容最匹配的機構清單。

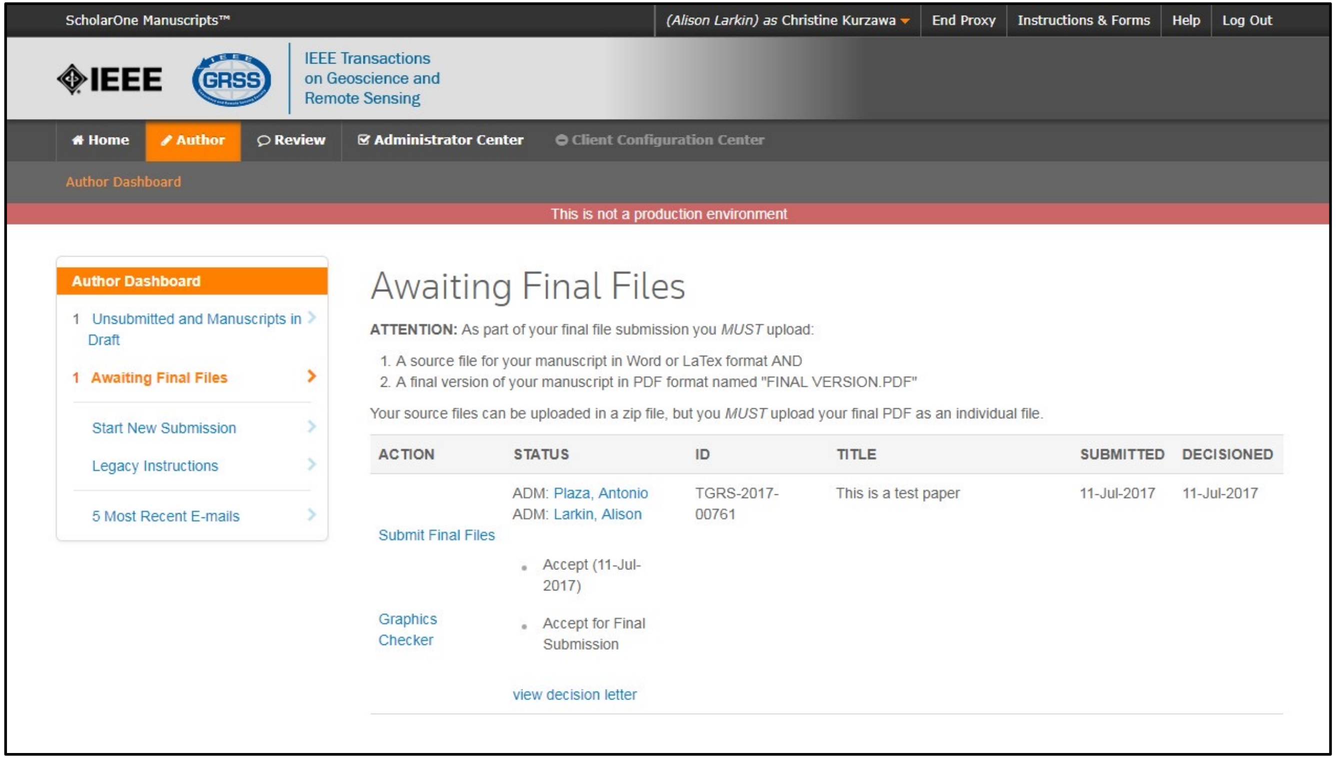
作者若採用Ringgold ID匹配，則需選擇學校**限定範圍的帳號**，詳情可見圖書館通知或諮詢我們。

如果作者未將所屬機構與Ringgold 綁定，則會顯示一條警告消息。

稿件錄用

- 如果稿件被錄用，作者將被要求上傳最終文檔並選擇版權許可。
- 此時作者可聯繫 ieee_oa@hintoninfo.com，提前確認APC優惠情況。

稿件錄用後 – 上傳最終文檔



Awaiting Final Files

ATTENTION: As part of your final file submission you *MUST* upload:

1. A source file for your manuscript in Word or LaTex format AND
2. A final version of your manuscript in PDF format named "FINAL VERSION.PDF"

Your source files can be uploaded in a zip file, but you *MUST* upload your final PDF as an individual file.

ACTION	STATUS	ID	TITLE	SUBMITTED	DECISIONED
Submit Final Files Graphics Checker	ADM: Plaza, Antonio ADM: Larkin, Alison • Accept (11-Jul-2017) • Accept for Final Submission view decision letter	TGRS-2017-00761	This is a test paper	11-Jul-2017	11-Jul-2017

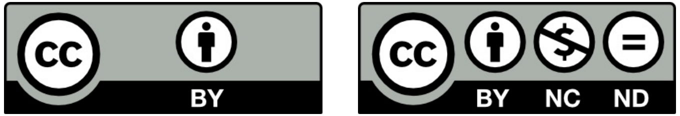
稿件錄用後 – 選擇版權許可

錄用後，系統將提示作者使用電子版權表格（eCF）選擇其版權許可：

- 傳統許可（將版權轉讓給出版商，文章以讀者付費模式發佈）
- **CC BY 4.0** 許可（作者保留版權，文章以開放取用方式發佈）
- **CC BY NC-ND** 許可（比 CC BY 更嚴格的許可，文章不得用於商業目的，也不得以任何方式更改文章）

在完全 OA 期刊上發表論文的作者可以選擇 CC BY 或 CC BY NC-ND 許可。

作者應確認所屬機構或研究資助機構對許可設置的限制。



https://creativecommons.org/about/cclicenses/

Evaluation of Thermal Imaging on Embedded GPU Platforms for Application in Vehicular Assistance Systems

Publisher: IEEE

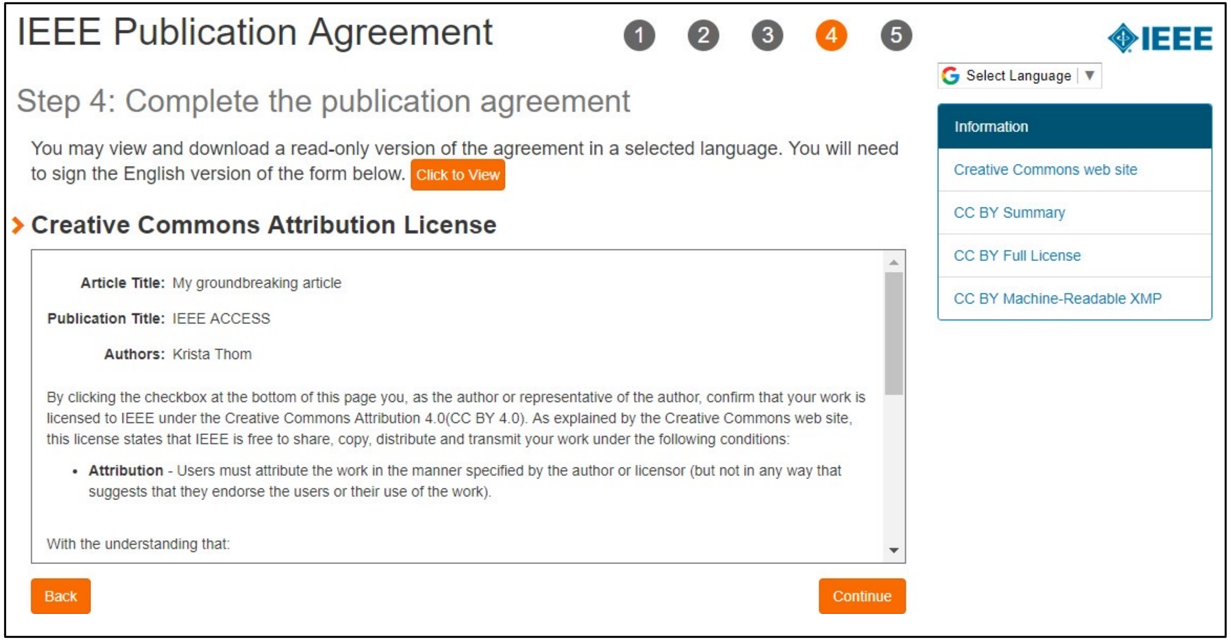
Muhammad Ali Farooq; Waseem Shariff; Peter Corcoran

Open Access

Under a Creative Commons License

IEEE Electronic Copyright Form (eCF)

1. 確認文章詳細資訊正確無誤
2. 確認文章原創性
3. 作者須同意支付文章處理費（APC）
4. 選擇 CC BY 許可類型並簽署相應授權合約
5. 下載授權合約的副本



IEEE Publication Agreement

Step 4: Complete the publication agreement

You may view and download a read-only version of the agreement in a selected language. You will need to sign the English version of the form below. Click to View

› Creative Commons Attribution License

Article Title: My groundbreaking article

Publication Title: IEEE ACCESS

Authors: Krista Thom

By clicking the checkbox at the bottom of this page you, as the author or representative of the author, confirm that your work is licensed to IEEE under the Creative Commons Attribution 4.0(CC BY 4.0). As explained by the Creative Commons web site, this license states that IEEE is free to share, copy, distribute and transmit your work under the following conditions:

- **Attribution** - Users must attribute the work in the manner specified by the author or licensor (but not in any way that suggests that they endorse the users or their use of the work).

With the understanding that:

RightsLink for Scientific Communications (RLSC)

- 所有APC流程都通過 RLSC 處理。
- RLSC將自動為符合資質的通訊作者向機構提交申請使用APC Token支付。
- 適用聯盟優惠的作者將收到Hinton發送之藍新金流APC支付通知
- 機構管理員對申請進行批復後，作者將收到答覆郵件。

IEEE
Advancing Technology for Humanity

Your article has been accepted and will be published open access

Dear Mr. Ruben Garcia Alia,

Congratulations on being accepted for publication in *IEEE Geoscience and Remote Sensing Letters* for the following manuscript:

Manuscript DOI: 10.1109/JTEHM.2019.529447
Manuscript ID: TNS-003417-445
Manuscript Title: This is a touch free OA only profile test
Published by: Institute of Electrical and Electronics Engineers (IEEE)
Total Charges Covered: 2045.00 USD

Funding for your open access publication charges has been covered by CCC University based on an agreement between CCC University and Institute of Electrical and Electronics Engineers (IEEE).

If there are any additional publication charges available to you, such as page or color charges, we will send a payment link for those charges under separate cover.

Sincerely,
Institute of Electrical and Electronics Engineers (IEEE)

Tel.: +1-877-622-5543 / +1-978-646-2777
IEEESupport@copyright.com
www.copyright.com

Copyright Clearance Center | RightsLink®

IEEE

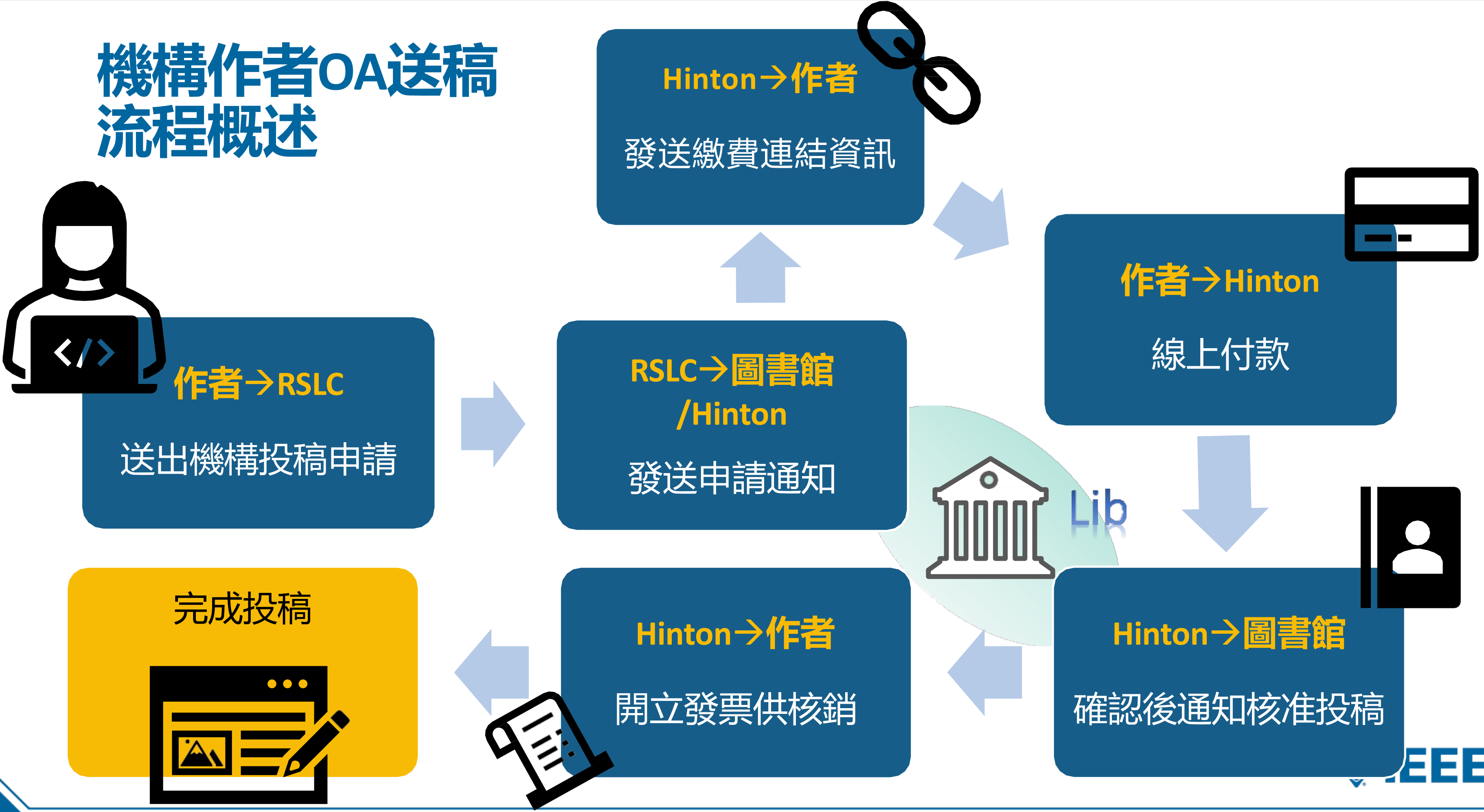
HINTON INFORMATION SERVICES | IEEE

Get Published in the *IEEE Open Journals*

Gold OA 聯盟投稿方案

for CONCERT

機構作者OA送稿流程概述



作者→RSLC

送出機構投稿申請

RSLC→圖書館/Hinton

發送申請通知

Hinton→作者

發送繳費連結資訊

作者→Hinton

線上付款

Hinton→圖書館

確認後通知核准投稿

Hinton→作者

開立發票供核銷

完成投稿

作者收到APC繳納通知 → APC繳納專頁

親愛的______作者您好

恭喜您的稿件(稿件 title)即將於(期刊 title)發表。

您的投稿適用 CONCERT 學術聯盟之優惠方案，得享 APC 均一優惠費率 USD $ 1,560，選擇適合的付款方式，並可取得電子發票以利經費報銷。

請透過方案專屬之藍新金流繳費連結選擇支付方式，並依畫面指示完成繳費(系統顯示金額已轉換為等值台幣)，繳費成功後您將會陸續收到 1)系統繳費完成通知信、2)學校方案支援申請成功通知信及 3)台幣電子發票證明聯。

若您於過程中需要任何協助，歡迎透過客服專線(tel)及客服信箱(IEEE_OA@hintoninfo.com)與我們聯繫，我們會盡快為您處理。

IEEE Gold OA APC

人氣:0

恭喜您的著作即將出版
付款人email請與通訊作者投稿email一致
請註明發票抬頭及/或統編

- https://core.newebpay.com/EPG/ieee_oa_apc/YPnWRP

作者於付款頁面填寫資料並完成APC繳納

付款人資訊 *為必填欄位

* 姓名：

* 聯絡電話：

* 選擇縣市：縣市 鄉鎮市區 郵遞區號

* 聯絡地址：

* 電子信箱：

發票/收據資訊：●發票 ○收據

發票資訊：□ 須統一編號

發票/收據抬頭：

統一編號：

收件人資訊 ● 同付款人 ○ 修改

留言給商店

- 以投稿時email為依據
- 輸入抬頭統編
- 付款成功將收到藍新金流付款完成通知信

機構管理員收到Token放行通知 → 登入後台點選Approve

Results per page: 25 Results 1 - 25 of 240

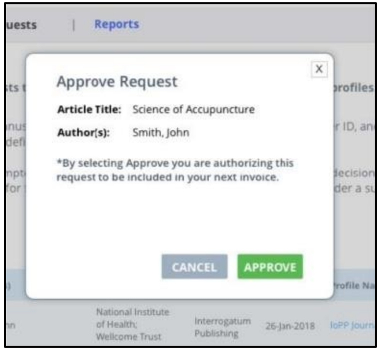
	Order Date	Article Title	Primary Author	Primary Author Email & Affiliation	Publisher	Profile Name	Total Fees Due	Status	Actions
›	13-Dec-2021	The unexpected narrowness of eccentric debris rings: a sign of eccentricity during the protoplanetary disc phase	Kennedy, Grant M	robinson@copyright.com Univeristy of Warwick 417804	Replica Publishing	AR Profile _1	0.00 USD	Pending	APPROVE DENY

親愛的機構管理員您好

感謝您協助推行 IEEE Gold OA 聯盟投稿方案。

貴校作者(作者名)的稿件(稿件 title)已獲(期刊 title)收錄，並完成 APC 支付程序
請協助登入管理後台並核准(Approve)該篇文獻之申請。

若您於過程中需要任何協助，歡迎透過客服專線(tel)及客服信箱
(IEEE_OA@hintoninfo.com)與我們聯繫，我們會盡快為您處理，謝謝。



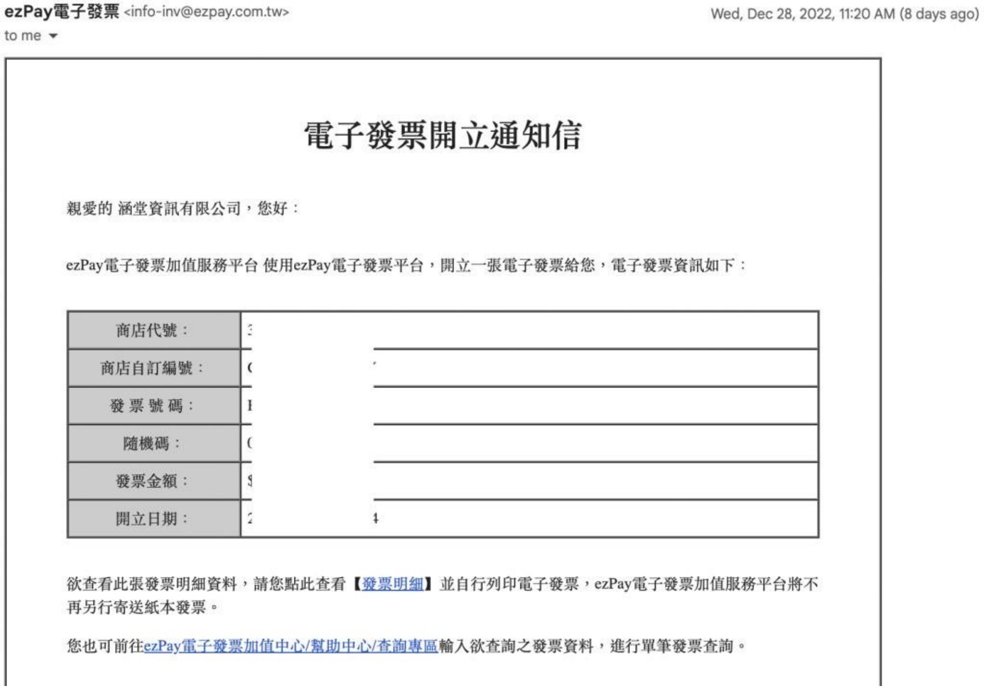
Approve Request

Article Title: Science of Accupuncture

Author(s): Smith, John

*By selecting Approve you are authorizing this request to be included in your next invoice.

作者收到ezPay電子發票開立通知信及RSLC核准通知



ezPay電子發票 <info-inv@ezpay.com.tw>
to me

Wed, Dec 28, 2022, 11:20 AM (8 days ago)

電子發票開立通知信

親愛的 涵堂資訊有限公司，您好：

ezPay電子發票加值服務平台 使用ezPay電子發票平台，開立一張電子發票給您，電子發票資訊如下：

商店代號：	[redacted]
商店自訂編號：	[redacted]
發 票 號 碼：	[redacted]
隨機碼：	[redacted]
發票金額：	[redacted]
開立日期：	[redacted]

欲查看此張發票明細資料，請您點此查看【發票明細】並自行列印電子發票，ezPay電子發票加值服務平台將不再另行寄送紙本發票。

您也可前往ezPay電子發票加值中心/幫助中心/查詢專區輸入欲查詢之發票資料，進行單筆發票查詢。

更多相關資源

- IEEE Open 網站
  - https://open.ieee.org/
- RightsLink for Scientific Communications: 作者資源
  - https://www.copyright.com/rlauthorrc/
- IEEE 作者中心
  - https://ieeeauthorcenter.ieee.org/
- 作者論文發佈指南
  - https://www.ieee.org/publications/rights/author-posting-policy.html

歡迎與我們交流！

何丹丹
IEEE大中華區客戶與資訊經理
IEEE Client Services Manager
d.he@ieee.org

IEEE資料庫在臺灣的合作夥伴
Hinton
IEEE@hintoninfo.com

OBRIGADO
gracias
どうも
ARIGATO
hvala
DANK U
takk
MERSI
merci
謝謝
obrigado
danke schön
köszi
danke
PALDIES
muchas gracias
ありがとう
TEŞEKKÜR EDERIM
MOLTE GRAZIE
GO RAIBH MAITH AGAT
grazas
GRAZZI
THANKS

THANK YOU

благодаря
TAK
どうも
qujan
TAK
благодаря
asante
muchas gracias
vielen dank
PALDIES
OBRIGADO
DANK U
mesi
danke
DANK U
감사합니다
köszi
благодаря
grazie
DZIEKI
TACK
Gràcies
TEŞEKKÜR EDERIM
muchas gracias
obrigado
спасибо
MULTUMESC
多謝
NA GODE